



**STANDALONE AND CONSOLIDATED
REPORT FOR THE FIRST HALF OF 2026
OF XTPL S.A. AND XTPL GROUP**

28/09/2026

Letter from the Management Board

Ladies and Gentlemen, Dear Shareholders and Investors

Since its inception, XTPL has operated with a global outlook, as the ultra-precise printing and dispensing technology we are developing addresses the needs of manufacturers of the most advanced electronics, concentrated primarily in East Asia, North America, and Europe. The vast majority of our sales today are directed to foreign markets, and we conduct projects with the greatest industrial potential with global partners and clients. In the first half of 2026, we took further significant steps toward building a global technology supplier in Poland for manufacturers of next-generation electronics. We continued our first industrial deployment in China, entered the Japanese market with UPD technology, commenced cooperation with Manz Asia in Taiwan, received our first order under the new ODRA systems business line, and, moreover, secured the Company's financial position.

The most advanced example of the industrial application of XTPL's technology remains the deployment carried out for one of the world's largest FPD display manufacturers in China. At the beginning of the year, we completed the delivery of the final head as part of the first batch of six UPD modules, which were integrated into machines operating on the end customer's production lines. The technology developed in Wrocław has thus successfully transitioned from the laboratory to the factory floor and has been validated in a real-world production environment.

Further evidence of the continued development of this project is the framework order for an additional 10 UPD modules, which we received after the end of the reporting period. This demonstrates that the initial implementation is not a one-off project and that the client is scaling up its use of our technology. The project will generate revenues from both sales of additional modules and consumables, supporting the development of a recurring revenue model. The order for a second, larger batch of UPD modules, in our assessment, does not exhaust the potential for further expansions in the future.

At the same time, work is progressing on the remaining industrial projects, among which semiconductors – including advanced packaging – and advanced printed circuit boards are gaining increasing importance. Japan became one of our key target markets in the first half of the year. Entry into this market is the result of several years of work on technology development, building its visibility, and establishing trust in XTPL among local partners and potential clients.

In June, we received the first order for a UPD module from Japan as part of Stage 4 of the process targeting ultimate industrial deployment, which will be used in yield management processes for advanced HDI and UHDI PCBs, as well as semiconductor substrates related to the advanced packaging area. Of particular significance is the use of copper as a conductive material in this project, as it increases the number of potential applications for our technology while simultaneously supporting the growth of the High Performance Materials line. The UPD module tested in this project also features a significantly higher specification, which translates into an almost two-fold increase in unit value compared to the UPD modules in the Chinese deployment.

After the end of the first half of the year, we received another independent order from Japan, this time for a DPS device and a laser system for a new industrial partner. Combined with another order for UPD modules for China, we view these events as tangible confirmation that the work carried out on the pipeline in prior periods is gradually translating into further customer purchasing decisions.

We are also expanding our presence in Asia through strategic partnerships. In the first half of the year, we established a partnership with Manz Asia, under which a DPS device was installed at the partner's center in

Taiwan. This allows us to present and test the technology closer to potential clients in one of the world's most important semiconductor ecosystems. This is a faster and less capital-intensive model than the one we are developing in the United States, where XTPL operates a dedicated Demo Center in Boston.

The second key area of focus in the first half of the year was the launch of commercialization of ODRA systems, which constitute XTPL's fourth business line and address our clients' needs by filling the gap between DPS devices and UPD modules integrated into large industrial machinery. ODRA is a standalone production system operating under the High-Mix Low-Volume model, and its specifications mean that an individual client may ultimately require a larger number of units.

In March, we received our first order for the ODRA system from an industrial client from Silicon Valley, operating in the advanced packaging sector and also partnering with the defense sector. The project team is achieving subsequent milestones related to the development of the first unit; however, the delivery and system settlement timeline agreed with the customer has been shifted from the fourth quarter of 2026 to the first quarter of 2027. This is the first sale of a new XTPL product, which will serve as an important reference for future interested clients. Therefore, we require additional time to perform comprehensive final testing prior to shipping the system to the client. In parallel, we are continuing advanced discussions with further potential clients.

Executing the ambitious pipeline of industrial projects and further scaling new business lines require properly secured financial backing. In the first half of the year, we raised PLN 19.5 million gross through a share issuance and signed an agreement for approximately PLN 10.1 million in grant funding from the NCBR. These funds currently allow us to finance industrial projects, the development of ODRA systems, R&D activities, and remaining business lines. This forms part of the implementation of the XTPL Strategy for 2026–2028, while in parallel, we are pursuing efforts to secure debt financing and a foreign strategic investor, i.e., a Taiwanese financial investor specializing in the semiconductor sector.

In the first half of 2026, we generated PLN 1.5 million in revenue from the sale of products and services and PLN 3.3 million in total revenue, compared to PLN 5.1 million and PLN 6.0 million, respectively, in the corresponding period of the previous year. EBITDA came in at PLN -7.6 million, and cash and cash equivalents stood at PLN 16.3 million as of the end of June. The first-half results do not yet reflect the full effect of the work conducted on our ongoing industrial projects, which have a long sales and implementation cycle, and whose pace largely depends on validation processes and end-client schedules beyond XTPL's direct control. The first half of 2026 brought an intensification of activities in XTPL's key areas, from the completion of the first implementation stage in China, through the commercialization launch of ODRA and the entry of UPD technology into the Japanese market, to expanding our presence in Taiwan and continuing work on other industrial projects. Events that occurred after June 30, in particular the subsequent order in Japan and the second, larger tranche of UPD modules for a client in China, demonstrate that a portion of this work is beginning to materialize.

With the growing maturity of our projects, we entered the second half of 2026, once again relying on historical seasonality, which typically manifests in a higher volume of orders during this period. We will consistently execute secured orders and advance further industrial projects to subsequent stages, fully aware that their pace remains largely dependent on the decision-making processes of global clients. However, the initial orders secured after the end of the half-year period and the growth of the pipeline provide us with a solid foundation to positively assess the direction in which XTPL is developing.

Although building a global deep tech company from Poland requires time, consistency, and patience, XTPL's technology is present today in projects implemented in China, Japan, Taiwan, and the United States, and the number of its potential applications is systematically growing. Our task remains to translate this growing global credibility, established pipeline, and accomplished work into further implementations, orders, and sales scale growth.

In closing, we would like to extend our sincere thanks to all our shareholders for their trust. We would also like to express our sincere gratitude to our clients, partners, and suppliers who support XTPL's growth in the global advanced electronics market, and above all, to our employees, whose expertise and commitment enable us to carry out demanding projects with partners around the world.

We invite you to thoroughly review the report for the first half of 2026 and to remain in contact with us through our Investor Relations Department and earnings calls.

Yours faithfully



Filip Graneck, PhD

A handwritten signature in blue ink, appearing to read 'Filip Graneck'.

Jacek Olszański

A handwritten signature in blue ink, appearing to read 'Jacek Olszański'.

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1. INFORMATION ABOUT THE REPORT AND A GLOSSARY OF TERMS AND ABBREVIATIONS

XTPL Spółka Akcyjna, a joint stock company having its registered office at ul. Legnicka 48E, 54-202 Wrocław, entered in the business register of the National Court Register kept by the District Court for Wrocław-Fabryczna, VI Commercial Division of the National Court Register under KRS No. 0000619674 ("**XTPL**", "**XTPL S.A.**", "**Company**", "**Entity**", "**Parent Company**", "**Issuer**"), NIP: 9512394886, REGON: 361898062.

As at June 30, 2026 ("**Balance Sheet Date**"), the share capital of XTPL S.A. amounted to PLN 294,987.70 and consisted of 2,949,877 shares with a nominal value of PLN 0.10 each ("**Shares**").

This document ("**Report**") contains the Report of the Management Board of XTPL S.A. on the activities of XTPL Group ("**Group**", "**XTPL Group**") and on the activities of XTPL S.A. for the first half of 2026 ("**Management Report**") for the first half of 2026 ("**Reporting Period**"), as well as the interim condensed standalone and consolidated financial statements of XTPL S.A. and the Group.

The Group includes the parent company and subsidiaries: XTPL Inc. with its registered office in the USA, and TPL Sp. z o.o. with its registered office in Wrocław, fully controlled by XTPL S.A. ("**Subsidiaries**", "**Subsidiary Undertakings**", "**XTPL Inc.**", "**TPL sp. z o.o.**"). During the reporting period, there were no changes in the structure of the Capital Group.

Unless indicated otherwise, the source of data in the Report is XTPL S.A. The Report publication date ("**Report Date**") is September 28, 2026.

The consolidated financial statements contained in the Report mean the interim condensed consolidated financial statements (including the Company and the Subsidiaries) for the period from January 1 to June 30, 2026 prepared in accordance with the International Financial Reporting Standards approved for application in the EU. The standalone financial statements contained in the Report mean the Parent Company's interim condensed standalone financial statements for the period from January 1 to June 30, 2026 ("**Reporting Period**"), prepared in accordance with the International Financial Reporting Standards approved for application in the EU.

"**WSE**" – Warsaw Stock Exchange: Giełda Papierów Wartościowych w Warszawie S.A.

"**CCC**" – the Act of September 15, 2000 – Commercial Companies Code.

"**Regulation on current and financial reports**" – the Finance Minister's Regulation of June 6, 2025 on current and financial reports released by the issuers of securities and the conditions for equivalent treatment of the information required by the laws of non-member states.

"**Articles of Association**" – the articles of association of XTPL S.A. available to the public at <https://ir.xtpl.com/pl/materialy/korporacyjne/>

"**Public Offering Act**" – the Act of July 29, 2005 on public offering, conditions governing the introduction of financial instruments to organized trading and public companies.

"**Accounting Act**" – the Accounting Act of September 29, 1994.

Due to the fact that the activities of XTPL S.A. have a dominant impact on the Group's operations, the information presented in the Management Board's Report relates both to XTPL S.A. and XTPL Group, unless stated otherwise.

Unless stated otherwise, the financial data are presented in thousands.

DEFINITIONS:

Ω (ohm) means a unit of electrical resistance

Ω / □ means resistance per square, or surface resistance

μm means micrometer, i.e. one millionth of a meter (1/1,000,000 m)

nm means nanometer, i.e. one billionth of a meter (1/1,000,000,000 m)

Adhesion means the tendency of different materials to stick together

Particle agglomeration means joining fine particles into larger parts

AMOLED (active-matrix organic light-emitting diode) means OLED diode with an active matrix

CAD means Computer Aided Design

CAGR means Compound Annual Growth Rate – the average rate of annual growth over the period under analysis, assuming that annual increases are added to the base value of the next period

Deposition means depositing a material locally

Ink formulation means precise formulation of the ink, giving it the desired physicochemical properties

FHE (Flexible Hybrid Electronics) means an electronic circuit made on a flexible substrate containing rigid electronic components, i.e. components not susceptible to bending

FPD (Flat-Panel Display) means a flat display

IP Intellectual property means intellectual and industrial property

Conductance means electrical conductivity, which is the inverse of resistance

Viscosity – a physical property of materials (fluids) that characterizes their internal frictional force during the flow of a fluid (for example, the viscosity of water, as a low-viscosity liquid, is about 1 cP, and the viscosity of honey varies from 2,000 to 10,000 cP)

Hydrophilic material means a material whose tendency is to attract water molecules

Hydrophobic material means a material whose tendency is to repel water molecules

Additive method means adding material to obtain a specific structure; it is the opposite of the subtractive method whereby material is subtracted to obtain a specific structure

micro-LED (uLED, μLED) means flat display technology based on semiconductor electroluminescent diodes (LED), in which each pixel is a microscopic LED diode

NDA (Non-Disclosure Agreement) means a confidentiality agreement

ODR (Open Defect Repair) means repairing defects in the form of broken conductive paths in the electronic system

OLED (organic light-emitting diode) means an LED based on organic material

UPD (ultra-precise dispensing) means a technology of ultra-precise printing of structures developed by the Company

PCB means printed circuit board made of insulating material with electronic connections, intended for assembly of electronic components

Sintering process means mutual binding of particles after heating them to a temperature lower than the temperature needed to melt them

Proof of concept means one of the first phases of cooperation involving the implementation of a client's idea to prove that it is fit for purpose

R&D means Research and Development

Resistance means electrical resistance

SEM means scanning electron microscope

Flash sintering means a method of curing a material using high-energy light within milliseconds

TEA means a **Technology Evaluation Agreement**

2. FINANCIAL HIGHLIGHTS

The selected financial data presented below contain basic figures (in thousands of zlotys and converted into euro) summarizing the financial position of the Company and XTPL Group.

Exchange rates applied

Balance sheet items have been converted at the average euro exchange rate announced by the National Bank of Poland, effective as at the balance sheet date.

The items of the income statement and the statement of cash flows were converted at the average EUR exchange rate being the arithmetic mean of the average EUR exchange rates announced by the National Bank of Poland and effective as at the last day of each completed month.

The table below contains the euro exchange rates used to convert the data in this report.

Exchange rates used in the financial statements	January–June 2026		January–June/ December 2025	
	EUR	USD	EUR	USD
for balance sheet items	4.2963	3.7708	4.2267	3.6016
for profit or loss and cash flow items	4.2522	3.6526	4.2208	3.8422

2.1 Selected standalone figures

Figures in PLN thousand	January 1 – June 30, 2026		January 1 – June 30, 2025	
	PLN	EUR	PLN	EUR
Net revenue from the sale of products and services	1,518	357	5,809	1,376
Revenue from grants	1,777	418	871	206
Profit (loss) on sales	-3,197	-752	-2,739	-649
Profit (loss) before tax	-10,513	-2,472	-11,124	-2,636
Profit (loss) after tax	-10,513	-2,472	-11,124	-2,636
Depreciation/amortization	3,468	816	2,754	652
Net cash flows from operating activities	-6,176	-1,453	-11,667	-2,764
Net cash flows from investing activities	-1,354	-318	-416	-99
Net cash flows from financing activities	16,795	3,950	-482	-114

Figures in PLN thousand	June 30, 2026		December 31, 2025	
	PLN	EUR	PLN	EUR
Equity	29,388	6,840	21,377	5,058
Short-term liabilities	9,829	2,288	10,351	2,449
Long-term liabilities	15,051	3,503	17,120	4,050
Cash and cash equivalents	15,628	3,637	6,363	1,505
Short-term receivables	5,669	1,319	7,462	1,765
Long-term receivables	1,185	276	1,232	291

2.2 Selected consolidated figures

Figures in PLN thousand	January 1 – June 30, 2026		January 1 – June 30, 2025	
	PLN	EUR	PLN	EUR
Net revenue from the sale of products and services	1,518	357	5,132	1,216
Revenue from grants	1,777	418	871	206
Profit (loss) on sales	-3,195	-751	-3,119	-739
Profit (loss) before tax	-11,846	-2,786	-12,805	-3,034
Profit (loss) after tax	-11,846	-2,786	-12,808	-3,035
Depreciation/amortization	3,493	821	2,779	658
Net cash flows from operating activities	-5,722	-1,346	-10,973	-2,600
Net cash flows from investing activities	-1,369	-322	-436	-103
Net cash flows from financing activities	16,761	3,942	-482	-114

Figures in PLN thousand Equity	June 30, 2026		December 31, 2025	
	PLN	EUR	PLN	EUR
Equity	26,130	6,082	19,403	4,591
Short-term liabilities	10,835	2,522	10,482	2,480
Long-term liabilities	15,049	3,503	17,120	4,050
Cash and cash equivalents	16,312	3,797	6,642	1,571
Short-term receivables	2,283	531	4,888	1,157
Long-term receivables	1,012	236	1,002	237

3. INTERIM CONDENSED STANDALONE FINANCIAL STATEMENTS

3.1 Interim condensed standalone statement of financial position

ASSETS	30.06.2026	31.12.2025
PLN '000		
Non-current assets	28,941	31,044
Property, plant and equipment	17,783	18,765
Intangible assets	9,973	11,047
Long-term receivables	1,185	1,232
Current assets	25,325	17,803
Inventories	3,777	3,735
Trade receivables	4,334	5,497
Other receivables	1,335	1,965
Cash and cash equivalents	15,628	6,363
Other assets	251	244
Total assets	54,266	48,847

EQUITY AND LIABILITIES	30.06.2026	31.12.2025
PLN '000		
Total equity	29,388	21,377
Share capital	295	265
Supplementary capital	35,455	38,448
Reserve capital	4,523	4,523
Retained earnings, including:	- 10,885	-21,859
- <i>current period result</i>	- 10,513	-21,487
Long-term liabilities	15,051	17,120
Long-term financial liabilities	13,390	14,133
Deferred income in respect of grants	1,658	2,985
Short-term liabilities	9,829	10,351
Trade liabilities	1,501	3,623
Short-term financial liabilities	2,757	2,582
Other liabilities	2,273	1,802
Deferred income in respect of grants	3,296	2,343
TOTAL EQUITY AND LIABILITIES	54,266	48,847

3.2 Interim condensed standalone statement of comprehensive income

INTERIM CONDENSED STANDALONE STATEMENT OF COMPREHENSIVE INCOME	01.01.2026 – 30.06.2026 PLN'000	01.01.2025 – 30.06.2025 PLN'000
Continued operations		
Revenue	3,295	6,680
Revenue from the sale of products and services	1,518	5,809
Revenue from grants	1,777	871
Cost of sales	6,492	9,419
Research and development expenses	4,082	5,873
Cost of finished goods sold	2,409	3,547
Gross profit (loss)	- 3,197	- 2,739
Marketing and selling costs	1,177	2,239
General and administrative expenses	5,636	5,661
Other operating income	4	135
Other operating costs	1	3
Operating profit (loss)	- 10,007	- 10,507
Financial revenues	124	145
Financial expenses	630	762
Profit/ loss before tax	- 10,513	- 11,124
Income tax	–	–
Net profit (loss) on continued operations	- 10,513	- 11,124
	–	–
Discontinued operations	–	–
Net profit (loss) on discontinued operations	–	–
Net profit (loss) on continued and discontinued operations	- 10,513	- 11,124
	–	–
Other comprehensive income	–	–
	–	–
Total comprehensive income	- 10,513	- 11,124
Net profit (loss) per share (in PLN)		
On continued operations		
Ordinary	-3.56	-4.20
Diluted	-3.56	-4.20
On continued and discontinued operations		
Ordinary	-3.56	-4.20
Diluted	-3.56	-4.20
number of shares to calculate ordinary profit (loss) per share	2,949,877	2,649,877
number of shares to calculate diluted profit (loss) per share	2,949,877	2,649,877

3.3 Interim condensed standalone statement of changes in equity

INTERIM CONDENSED STANDALONE STATEMENT OF CHANGES IN EQUITY PLN`000	Share capital	Supplementary capital	Reserve capital	Retained earnings	Total
As at January 1, 2026	265	38,448	4,523	- 21,859	21,377
Comprehensive income:	-	-	-	- 10,513	- 10,513
Profit (loss) after tax	-	-	-	- 10,513	- 10,513
Other comprehensive income	-	-	-	-	-
Transactions with owners:	30	- 2,993	-	21,487	18,524
Issue of shares	30	18,494	-	-	18,524
Sale of own shares	-	-	-	-	-
Incentive scheme	-	-	-	-	-
Profit distributions	-	- 21,487	-	21,487	-
Value of conversion rights under convertible bonds	-	-	-	-	-
As at June 30, 2026	295	35,455	4,523	- 10,885	29,388
As at January 1, 2025	265	59,312	2,386	-21,236	40,727
Comprehensive income:	-	-	-	-11,124	-11,124
Profit (loss) after tax	-	-	-	-11,124	-11,124
Other comprehensive income	-	-	-	-	-
Transactions with owners:	-	-20,864	-	20,864	-
Issue of shares	-	-	-	-	-
Incentive scheme	-	-	-	-	-
Profit distributions	-	-20,864	-	20,864	-
Value of conversion rights under convertible bonds	-	-	-	-	-
As at June 30, 2025	265	38,448	2,386	-11,496	29,603

3.4 Interim condensed standalone statement of cash flows

INTERIM CONDENSED STANDALONE STATEMENT OF CASH FLOWS	01.01.2026	01.01.2025
	–	–
	30.06.2026	30.06.2025
	PLN'000	PLN'000
Cash flows from operating activities		
Profit (loss) before tax	- 10,513	-11,124
Total adjustments:	4,337	-543
Depreciation/amortization	3,468	2,754
FX gains (losses)	–	-51
Interest and profit distributions (dividends)	576	195
Profit (loss) on investing activities	- 2	-155
Change in the balance of provisions	275	171
Change in the balance of inventories	- 42	507
Change in the balance of receivables	1,774	-1,801
Change in short-term liabilities, except bank and other loans	- 1,331	-1,198
Change in other assets	- 7	-94
Change in the balance of grants to be settled	- 373	-871
Incentive scheme valuation	–	–
Income tax paid	–	–
Other adjustments	–	–
Total cash flows from operating activities	- 6,176	-11,667
Cash flows from investing activities		
Inflows	58	24
Disposal of tangible and intangible assets	2	4
Repayment of long-term loans	–	–
Interest on financial assets	56	19
Outflows	1,412	440
Acquisition of tangible and intangible assets	1,412	440
Acquisition of financial assets	–	–
Long-term loans granted	–	–
Other investment outflows	–	–
Total cash flows from investing activities	- 1,354	-416
Cash flows from financing activities		
Inflows	18,590	107
Issue of shares	18,524	–
Bank and other loans	66	107
Other financial inflows	–	–
Outflows	1,795	589
Repayment of bank and other loans	–	–
Finance lease payments	1,163	297
Interest	632	292
Total cash flows from financing activities	16,795	-482
Total net cash flows	9,265	-12,566
Change in cash and cash equivalents:	9,265	-12,534
– change in cash due to FX differences	–	32
Cash and cash equivalents at the beginning of the period	6,363	26,921
Cash and cash equivalents at the end of the period, including:	15,628	14,355
– restricted cash	1	131

3.5 Notes

Note 1. Intangible assets

INTANGIBLE ASSETS	figures in PLN thousand	30.06.2026	31.12.2025
Acquired concessions, patents, licenses and similar rights		–	–
Intellectual property rights		–	–
Other intangible assets		803	1,000
Completed development		8,011	9,179
In-process development expenditure		1,159	867
Total (net)		9,973	11,047
Accumulated amortization		6,599	5,213
Total (gross)		16,572	16,260

All intangible assets are the property of the Company; none of these assets are used based on any rental, lease or a similar contract. The Company does not use its intangible assets as collateral. As of June 30, 2026, the Company had no agreements obliging it to purchase intangible assets. In 2026 and 2025, no impairment losses were recognized for intangible assets.

As at June 2026, under the item “Other intangible assets” the Company presents the net value of licenses held. As at June 30, 2026, under “Completed development”, the Company presents expenditure on completed development relating to:

- Development of a demonstration prototype of a laboratory printer: net amount PLN 1,107 thousand;
- R&D OLED hardware: net amount PLN 1,611 thousand;
- R&D 3D PRINT hardware: net amount PLN 2,273 thousand;
- UPD industrial printhead: net amount PLN 3,020 thousand.

Under the item “In-process development expenditure” as of June 30, 2026, the Company presents expenditure on development projects that have not yet been brought into use and which relate to:

- development costs related to copper ink in the gross amount of PLN 730 thousand;
- development costs related to extending the service life of nozzles used in DPS printers and UPD modules in the gross amount of PLN 429 thousand.

The table below presents the expenditures incurred on development during production in the period from January 1, 2026 to June 30, 2026, broken down by cost types.

	PLN ‘000
In-process development expenditure, including	
Salaries	155
External services	58
Materials	78
Other	–
Impairment allowances on capitalized expenditure	–
Total	292

Note 2. Property, plant and equipment and significant acquisitions of property, plant and equipment

PROPERTY, PLANT AND EQUIPMENT	figures in PLN thousand	30.06.2026	31.12.2025
Tangible assets, including:		17,231	18,323
Buildings, premises, rights to premises and civil and water engineering structures		14,161	15,059
Technical equipment and machines		190	257
Vehicles		120	81
Other tangible assets		2,760	2,927
Tangible assets under construction		552	441
Property, plant and equipment, net		17,783	18,765
Accumulated amortization		12,053	10,003
Property, plant and equipment, gross		29,836	28,768

Property, plant and equipment under construction consists of expenditure incurred on the UPD Pro head in the amount of PLN 254 thousand and the ODRA system in the amount of PLN 268 thousand.

Other property, plant and equipment consist of laboratory and measuring equipment (Group 8) used by employees of the R&D departments.

No tangible assets are used as collateral. In 2026 and 2025, no impairment losses were recognized for tangible assets.

As at June 30, 2026, the Company uses tangible assets under rental and lease agreements totalling PLN 14,838 thousand net.

TANGIBLE ASSETS LEASED	30.06.2026			31.12.2025		
	Gross value	Depreciation	Net value	Gross value	Depreciation	Net value
Buildings, premises, rights to premises and civil and water engineering structures	15,514	-1,383	14,132	17,498	- 2,439	15,059
technical equipment and machines	281	- 140	140	281	- 140	140
other tangible assets	560	- 175	385	1,139	- 568	571
vehicles	220	- 39	181	241	- 160	81
Total	16,575	- 1,738	14,838	19,159	- 3,308	15,851

The table below presents the acquisition of material items of property, plant and equipment.

SIGNIFICANT INCREASES IN PROPERTY, PLANT AND EQUIPMENT, AND LEASES	figures in PLN thousand	01.01.2026 - 30.06.2026	01.01.2025 - 31.12.2025
Other laboratory equipment		—	34
Office and laboratory space for rent, ul. Legnicka 48E		295	10,864
Nanoparticle size analyzer		—	200
Fume hoods		—	154
Precision scales		—	16
Demineralizers		—	21
Double-beam spectrophotometer		—	45
Chilled water unit		—	30
Homogenizator ARV-310P		—	84
Laboport vacuum system		—	19
XTPL DPS-ODR7 printer		172	—
Hydra multihead		386	—
Mazda CX-5 25 passenger car – lease		78	—
Microforge nozzle forming station		46	—
Micropipette beveler		12	—
Total significant acquisitions		989	11,468

Note 3. Significant liabilities on account of purchase of tangible assets

As of June 30, 2026, the Company did not have any concluded agreements obliging it to purchase fixed assets. The Company has liabilities arising from the rental and leasing of property, plant and equipment in the amount of PLN 15,814 thousand (including short-term liabilities of PLN 2,423 thousand and long-term liabilities of PLN 13,390 thousand).

The maturity period of liabilities is presented in the table below.

Year	Repayment period				short term	long term	Total
	up to 1 year	1 year to 3 years	3 to 5 years	above 5 years			
2026	2,423	4,877	5,633	2,880	2,423	13,390	15,814

Note 4 Changes in the classification of financial assets as a result of a change in the purpose or use of these assets

In the reporting period no changes were made in the classification of financial assets.

Note 5. Impairment allowance for financial assets, tangible assets, intangible assets or other assets and reversal of the impairment allowance

In the period presented, there were no impairment allowances on financial assets, property, plant and equipment, intangible assets or other assets or any reversal of such impairment allowances.

Note 6. Long-term receivables

Long-term receivables	figures in PLN thousand	30.06.2026	31.12.2025
Loans granted		–	–
Security deposits		1,012	1,002
Shares		–	–
For equipment used under rental agreements		173	230
Total long-term receivables		1,185	1,232

As of June 30, 2026, under the item “Security deposits” in the amount of PLN 1,012 thousand, the Company presents expenditure related to the lease of office and laboratory space in the amount of PLN 982 thousand, whereas the amount of PLN 30 thousand relates to a performance bond deposit with a Client.

Under the item “Equipment used under rental agreements”, the Company presents a lease agreement for a printer [DPS] concluded with its subsidiary, XTPL Inc. The presented value refers to capital repaid in installments, which for balance sheet purposes was recognized in accordance with the principles of IFRS 16. According to the agreement, the lease began in July 2024, the lease period was set at 48 months.

Note 7. Impairment allowance on inventories to their net recoverable amount and reversal of the allowance

In the Reporting Period, no write-down (impairment allowance) of inventories was created or reversed.

Note 8. Change in the balance of provisions

CHANGE IN THE BALANCE OF PROVISIONS	figures in PLN thousand	01.01.2026 - 30.06.2026	01.01.2025 - 31.12.2025
Balance at the beginning of the period		481	398
increased/ created		275	83
utilization		–	–
release		–	–
Balance at the end of the period		756	481

The change in provisions presented in the table above relates to provisions created for unused annual leaves by the Company's employees. The above provisions are presented in the statement of financial position under other liabilities.

Note 9. Share capital

On March 30, 2026, the Management Board of the Issuer submitted a statement determining the amount of the Company's share capital in the Articles of Association, in such way that the Company's share capital amounts to PLN 294,987.70 (two hundred ninety-four thousand nine hundred and eighty-seven zloty and 70/100) and is divided into 2,949,877 ordinary bearer shares with a nominal value of PLN 0.10 (ten groszy) each, including:

REF.	number of shares	series
1	670,000	A
2	300,000	B
3	30,000	C
4	198,570	D
5	19,210	E
6	19,210	F
7	68,720	G
8	68,720	H
9	10,310	I
10	5,150	J
11	10,310	K
12	140,020	L
13	155,000	M
14	47,000	N
15	41,400	O
16	42,602	P
17	78,000	S
18	125,000	T
19	45,655	U
20	275,000	V
21	300,000	X
22	300,000	Y

Below, the Company presents information summarizing the public offering (in the form of a private placement) of series Y ordinary bearer shares issued pursuant to resolution No. 03/03/2026 of the Extraordinary General Meeting of the Company of March 9, 2026 on increasing the Company's share capital by issuing series Y ordinary bearer shares (fully disapplying shareholders' preemption rights), amending the Company's Articles of Association and applying for the admission and introduction of those shares to trading on the regulated market ("Series Y Shares"):

1. Dates of commencement and completion of the subscription for the Series Y Shares: Subscription agreements for Series Y Shares were concluded on March 16–20, 2026.
2. Date of allotment of the Series Y Shares: The subscription of Series Y Shares was carried out in the form of a private placement, so no shares allocations were made within the meaning of Article 434 of the Commercial Companies Code. On March 25, 2026, the Management Board of the Company submitted a statement regarding the determination of the Company's share capital in the Articles of Association.
3. Number of Series Y Shares subscribed for: The private placement for Series Y Shares included no fewer than 1 and no more than 300,000 Series Y Shares.
4. Reduction rates in individual tranches: The Series Y Shares were subscribed for by investors through a private subscription; therefore, no allocation reduction was necessary. The subscription of the Series Y Shares was not divided into tranches.
5. Number of Series Y Shares for which subscription offers were accepted: A total of 300,000 Series Y Shares were subscribed for and accepted in the private placement.
6. Number of Series Y Shares taken up in the completed private placement: 300,000 Series Y Shares were taken up in the private placement.
7. Price at which the Series Y Shares were taken up:
The issue price per Series Y share was PLN 65 (sixty-five zloty) per Series Y share. The total issue price of all Series Y shares subscribed by investors amounted to PLN 19,500,000 (nineteen million five hundred thousand zloty).
8. Number of investors who entered into subscription agreements for Series Y Shares: Subscription agreements for Series Y Shares were executed with a total of 27 investors.
9. Names of the sub-underwriters who took up Shares under the sub-underwriting agreements, specifying the number of Series Y Shares they subscribed for, together with the actual price per Series Y Share (issue or sale price, net of the fee for subscribing to the financial instrument unit under the sub-underwriting agreement, paid by the sub-underwriter): No Series Y Shares were taken up by sub-underwriters.
10. Value of the completed placement or sale: The value of the Series Y share subscription (defined as the product of the number of Series Y shares subscribed for and their issue price) amounted to PLN 19,500,000 (nineteen million five hundred thousand zloty).
11. Total costs recognized as expenses of the Series Y Share issuance: As of the date of this report, the total estimated costs recognized as expenses of the Series Y Share issuance amounted to PLN 975,922.00, including:
 - a) preparation and execution of the offer: PLN 975,922.00;
 - b) remuneration of underwriters: not applicable;
 - c) preparation of the prospectus, including advice: not applicable;
 - d) offer promotion: not applicable.
12. The average estimated cost of conducting the subscription per Series Y Share amounts to: PLN 3.25.
13. Method of payment for the subscribed Series Y Shares:
The Series Y Shares were paid for in cash.
Series Y shares were admitted to trading on the Warsaw Stock Exchange (GPW) on April 17, 2026, under ISIN code PLXTPL000018.

Note 10. Transfers between individual fair value hierarchy levels in respect of financial instruments

In the reporting period no transfers took place between individual fair value hierarchy levels in respect of financial instruments.

The Company does not identify financial instruments classified within Level 1 or Level 2 of the fair value hierarchy.

Note 11. Fair value of the individual classes financial assets and liabilities

		Book value		Fair value	
	Category	30.06.2026	31.12.2025	30.06.2026	31.12.2025
Financial assets					
Loans granted	WwgZK	14	14	14	14
Trade receivables	WwgZK	4,334	5,497	4,334	5,497
Equipment lease receivables	according to IFRS 16	305	351	305	351
Other receivables	WwgZK	2,201	2,831	2,201	2,831
Cash and cash equivalents	WwgZK	15,628	6,363	15,628	6,363
Total		22,482	15,057	22,482	15,057
Financial liabilities					
Interest bearing bank and other loans	PZFwgZK	335	304	335	304
Bond liabilities	WwWGpWF	–	–	–	–
Lease liabilities	according to IFRS 16	15,814	16,413	15,814	16,413
Trade liabilities	PZFwgZK	1,501	3,623	1,501	3,623
Other liabilities	PZFwgZK	1,501	1,321	1,501	1,321
Total		19,151	21,661	19,151	21,661

Abbreviations used:

WwgZK – Measured at amortized cost

PZFwgZK – Other liabilities measured at amortized cost

WwWGpWF – Financial assets/ liabilities measured at fair value through profit or loss

The fair value of financial instruments held by the Company as at June 30, 2026 and December 31, 2025 did not differ significantly from the value presented in the financial statements for the respective years for the following reasons:

- with regard to short-term instruments, the potential effect of the discount is not material;
- the instruments relate to the transactions concluded on market terms.

Note 12. Explanations to the statement of cash flows

Presented below are explanations to selected items of the statement of cash flows.

	figures in PLN thousand	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
PBT presented in the statement of comprehensive income		- 10,513	-11,124
PBT presented in the statement of cash flows		- 10,513	-11,124

INTEREST AND DIVIDENDS IN THE STATEMENT OF CASH FLOWS	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Realized interest on financing activities	632	214
Realized interest on investing activities	- 56	-19
Unrealized interest on financing activities	–	–
Unrealized interest on investing activities	–	–
Total interest and dividends:	576	195

CHANGE IN THE BALANCE OF RECEIVABLES	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Change in the balance of trade receivables	870	-1,801
Other receivables	904	–
Loans granted	–	–
Total change in the balance of receivables:	1,774	-1,801

CHANGE IN THE BALANCE OF LIABILITIES	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Change in the balance of trade liabilities	- 2,121	-1,198
Other liabilities	791	–
Change in employee benefit provisions	–	–
Total change in the balance of liabilities:	- 1,331	-1,198

Cash and cash equivalents at the end of the period	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Statement of cash flows	15,628	14,355
Statement of financial position	15,628	14,387

Inflow from grants	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
– to operations	1,434	–
– to assets	–	–
– advance payments not settled/ (settled)	–	–
Total grant proceeds	1,434	–

The difference between the balance of cash presented in the statement of financial position as at June 30, 2026 and the value of cash presented in the statement of cash flows results from the exchange rate differences relating to the valuation of cash held in the bank accounts.

Proceeds from grants mainly comprise funds received under the STEP and Ultrasens grant projects.

Note 13. Revenue

REVENUE	figures in PLN thousand	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Research and development revenue		270	438
Revenue from the sale of products		1,248	5,320
Revenue from sales – leases		–	–
Revenues from the sale of goods		–	51
Revenue from grants		1,777	871
Total Revenue		3,295	6,680

During the reporting period, the Company recognized grant revenue of PLN 1,777 thousand.

In accordance with IAS 20, grants to assets are also recognised in the liabilities of the statement of financial position at the balance sheet date. Grants to depreciable assets will be recognized in the Company's profit or loss over the individual periods in proportion to the recognition of depreciation on those assets.

Note 14. Operating costs

OPERATING COSTS	figures in PLN thousand	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Depreciation/ amortization, including		3,468	2,754
– depreciation of tangible assets		2,082	1,704
– amortization of intangible assets		1,386	1,050
Use of raw materials and consumables		1,447	2,366
External services		2,615	4,062
Cost of employee benefits		5,711	7,528
Taxes and charges		129	153
Other costs by type		226	428
Value of goods and materials sold		–	–
Total costs by type, including:		13,597	17,292
Items reported as research and development costs		4,082	5,873
Items reported as cost of finished goods sold		2,409	3,547
Marketing and selling costs		1,177	2,239
Items reported as general and administrative expenses		5,636	5,661
Change in product inventories		–	-424
Cost of producing services for internal needs of the entity		292	397

Note 15. Related party transactions

01.01.2026-30.06.2026	figures in PLN thousand	To related parties	To joint ventures	To key management personnel*	To other related entities **
Purchase of services		48	–	–	–
Loans granted		–	–	–	–
Revenue from the sale of products		41	–	–	–
Revenue from the sale of services		–	–	–	–
Revenue from equipment lease		–	–	–	–
Cost of products sold		19	–	–	–
Financial revenues - interest on loans and printer lease agreement		14	–	–	–

01.01.2025-30.06.2025	figures in PLN thousand	To related parties	To joint ventures	To key management personnel*	To other related entities **
Purchase of services		24	–	–	–
Loans granted		–	–	–	–
Revenue from the sale of products		3,318	–	–	–
Revenue from the sale of services		51	–	–	–
Revenue from equipment lease		–	–	–	–
Cost of products sold		1,083	–	–	–
Financial revenues - interest on loans and printer lease agreement		19	–	–	–

* the item includes persons who have the authority and responsibility for planning, managing and controlling the company's activities

** the item includes entities linked through key management

Terms of related party transactions

Sales to and purchases from related parties are made on an arm's length basis. Any overdue liabilities/receivables existing at the end of the period are interest-free and settled on cash or non-cash basis. The Company does not charge late interest from other related entities. Receivables from or liabilities to related parties are not covered by any guarantees given or received. They are not secured in any other way either.

Note 16. Deferred tax

Deferred income tax assets due to negative temporary differences	Statement of financial position as at		Impact on the statement of comprehensive income
PLN '000	30.06.2026	31.12.2025	01.01.2026 - 30.06.2026
Due to differences between the carrying amount and the tax value:			
Accruals for unused annual leaves	3	—	—
Provision for salaries	—	—	—
Provision for the cost external services	—	—	—
Provision for extra social security costs	—	—	—
Leased tangible assets	—	—	—
Exchange differences on translation	—	—	—
Total deferred tax assets	3	—	—
Offset against the deferred tax liability	3	—	—
Net deferred tax assets	—	—	—

Deferred tax liability caused by positive temporary differences	Statement of financial position as at		Impact on the statement of comprehensive income
PLN '000	30.06.2026	31.12.2025	01.01.2026 - 30.06.2026
Due to differences between the carrying amount and the tax value:			
Interest on loans and deposits	3	—	—
Leased tangible assets	—	—	—
Total deferred tax liability	3	—	—
Offset against the deferred tax assets	3	—	—
Net deferred tax liability	—	—	—

Negative temporary differences and tax losses for which no deferred tax asset was recognized in the statement of financial position:	Basis for generating the asset at the end of the period June 30, 2026	Basis for generating the asset at the end of the period December 31, 2025	Date of expiry of negative temporary differences, tax losses
In respect of:			
Salaries	41	305	
Accruals for unused annual leaves	495	479	
Provision for the cost external services	213	258	
Leased tangible assets	1,035	674	
Provision for extra social security costs	87	—	
Exchange differences on translation	45	—	

Note 17. Objectives and rules of financial risk management

The Company is exposed to risk in each area of its operations. With understanding of the threats that originate through the Company's exposure to risk and the rules for managing these threats the Company can run its operations more effectively. Financial risk management includes the processes of identification, assessment, measurement and management of this risk. The main financial risks to which the Company is exposed include:

- Market risks:
- The risk of changes in market prices (price risk)
- The risk of changes in foreign exchange rates (currency risk)
- The risk of changes in interest rates (interest rate risk)
- Liquidity risk;
- Credit risk.

The risk management process is supported by appropriate policies, organisational structure and procedures.

MARKET RISK

The Company actively manages the market risk to which it is exposed. The objectives of the market risk management process are to:

- limit the volatility of pre-tax profit/loss
- increase the probability of achievement of the budget plan
- maintain the Company in good financial condition
- support the strategic decision-making process in the area of investment activity, taking into account the sources of investment financing

All market risk management objectives should be considered jointly, and their achievement is primarily dependent on the Company's internal situation and market conditions.

PRICE RISK

In the period from January to June 2026, the Company did not invest in any debt instruments and, therefore, is not exposed to any price risk.

CURRENCY RISK

The Company is exposed to currency risk in respect of the transactions it concludes. Such risk arises when the entity makes purchases in currencies other than the valuation currency, mainly in USD and EUR.

Part of the Company's settlements is denominated in foreign currencies. As at June 30, 2026, the Company has assets denominated in foreign currencies, which include trade receivables. The value of the liabilities in foreign currencies as at the balance sheet date relates to trade liabilities. Therefore, there is a risk related to the negative impact of FX changes on the financial results achieved by the Company. In order to mitigate the possible effects of exchange rate fluctuations, the Company monitors the current exchange rates on an ongoing basis.

INTEREST RATE RISK

Deposit transactions are made with institutions with a strong and stable market position. The instruments used – short-term, fixed-rate transactions – ensure full security.

Consequently, the recent interest rate hikes do not affect the Company's operations. In view of the above, the Company did not apply interest rate hedges, considering that interest rate risk is not significant for its business.

LIQUIDITY RISK

The Company monitors the risk of a lack of funds using the periodic liquidity planning tool. This tool takes into account the maturity dates of both investments and financial assets (e.g. accounts receivable, other financial assets) and projected cash flows from operating activities.

The Company seeks to maintain a balance between continuity and flexibility of financing by using different sources of financing, such as finance leases.

The Company is exposed to financing risk due to the possibility that in the future it might not receive sufficient cash to fund commercialization of its research and development projects.

In the Reporting Period, the Company had a PLN 600 thousand overdraft agreement. The facility was used rarely and for a short term only.

Santander Bank Polska: limit of PLN 200 thousand until April 13, 2027;

ING Bank Śląski: limit of PLN 400 thousand until March 31, 2027;

CREDIT RISK

In order to mitigate the credit risk related to cash and cash equivalents deposited in banks, loans granted, deposits paid in respect of rental contracts and performance security as well as trade credit, the Company:

- cooperates with banks and financial institutions with a known financial position and established reputation
- analyzes the financial position of its counterparties based on publicly available data as well as through business intelligence agencies
- in the event of a risk of customer insolvency, the Company secures its proceeds with bank guarantees or corporate guarantees.

Note 18. Material settlements on account of court cases

At the reporting date there are no court proceedings pending whose value would be considered material. Furthermore, in the period covered by the interim report no material settlements were made on account of court cases.

Note 19. Information about changes in the economic position and operating conditions which might have a material impact on the fair value of the financial assets and liabilities, whether those assets and liabilities are recognized at fair value or at adjusted purchase price (amortized cost)

In the period from January 1, 2026 to June 30, 2026, no significant changes were identified in the economic position or operating conditions which would have a material impact on the fair value of the Company's financial assets and liabilities.

Note 20. Information about changes in contingent liabilities and contingent assets and non-disclosed liabilities arising from contracts in relation to the last reporting period

Contingent liabilities granted by the Company were in the form of promissory notes together with promissory note declarations to secure the contracts for co-financing projects financed by the EU.

At the Balance Sheet Date and until the date of approval of the financial statements for publication, no events occurred that could result in materialisation of the above contingent liabilities. As at the date of approval of the financial statements there were no undisclosed liabilities resulting from any agreements of material value. In addition, the Entity issues promissory notes to secure its liabilities under lease agreements up to the amount of such liabilities.

The increase in the value of contingent liabilities as of June 30, 2026, by the amount of PLN 505 thousand is related to the receipt of a grant tranche under the project FENG.05.01-IP.01-001P/25.

CONTINGENT LIABILITIES	30.06.2026	31.12.2025
Promissory notes	14,638	14,133
Total contingent liabilities	14,638	14,133

Note 21. Incentive scheme

In the Reporting Period, the Company did not grant any instruments or recognize in the interim condensed statement of comprehensive income any cost of the incentive scheme for employees and collaborators based on the Parent Company's shares.

Note 22. Information about seasonality of business and cycles

The Company's activity is not subject to seasonality or business cycles.

Note 23. Extraordinary factors which occurred in the reporting period with an indication of their impact on the financial statements

In the reporting period, no extraordinary events occurred that would affect the interim condensed financial statements.

Note 24. Information on issue, redemption and repayment of debt and equity securities

In the first half of 2026, the Company decided to initiate actions aimed at securing funding for the Company based on raising funds through the issuance of new shares (ESPI Current Report No. 3/2026 of February 9, 2026).

For more information on the issuance of new shares, see section Note 9 Share capital and section 5.9.2 Issuance of securities this report.

Note 25. Dividend paid or declared, in total and per share, with a division into ordinary and preference shares

In the reporting period the Company did not pay or declare any dividends.

Note 26. Operating segments

The entity's reporting segments are based on product groups.

As at the Reporting Date, the Company distinguished three product groups:

- Delta Printing System laboratory printers and UPD modules
- silver-based conductive nanoinks;
- research services related to printing on client-supplied substrates in the manner specified by the client, in order to demonstrate the suitability of the XTPL technology to solve technological production problems (Proof of Concept).

SALES REVENUE BY SEGMENTS	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Sale and lease of printers	1,043	4,667
Nanoinks and other consumables	205	704
Leasing services	–	–
Research and development services	270	438
TOTAL	1,518	5,809

As at June 30, 2026, the Company presents in its statement of financial position PLN 3,995 thousand in trade receivables and PLN 1,391 thousand representing costs incurred on work in progress. The above amounts relate to the segment of laboratory printers – the Delta Printing System – the UPD modules.

In its statement of financial position, the Group presents PLN 339 thousand in respect of trade receivables and PLN 53 thousand relating to expenditure on work in progress. The above amounts relate to the inks and consumables segment.

As of June 30, 2026, the Company has receivables towards the subsidiary under a laboratory equipment lease agreement in the amount of PLN 305 thousand (including long-term PLN 173 thousand, short-term PLN 131 thousand).

Revenue from sales recognized by the Company in the first half of 2026, in the amount of PLN 1,518 thousand, relates to transactions concluded with foreign clients.

The following countries had the largest percentage share in sales: 35.5% Israel, Taiwan 19.7%, China 15.1%, Japan 11.0%, Germany 4.5%, USA (intercompany sales) 4.4%, Portugal 2.5%, UK 1.5%, Romania 1.5%, other countries 4.1%.

As at December 31, 2025, the Company presented in its statement of financial position PLN 5,338 thousand in trade receivables and PLN 1,197 thousand representing costs incurred on work in progress. The above amounts relate to the segment of laboratory printers – the Delta Printing System, and UPD modules.

As at December 31, 2025, the Company showed in the statement of financial position PLN 156 thousand concerning trade receivables in the inks and consumables segment.

As at December 31, 2025, the Company showed in the statement of financial position PLN 3 thousand concerning trade receivables in the R&D segment.

As of December 31, 2025, the Company had receivables towards the subsidiary under a laboratory equipment lease agreement in the amount of PLN 351 thousand (including long-term PLN 230 thousand, short-term PLN 121 thousand).

Revenue from sales recognized by the Company in the first half of 2025, in the amount of PLN 5,746 thousand, relates to transactions concluded with foreign clients (representing 98.9%). In the first half of 2025, the Company recognized PLN 63 thousand from sales transactions with domestic entities (representing 1.1%).

The following countries had the largest percentage share in sales: 60.3% USA (intercompany sales), China 15.4%, UK 12.8%, Germany 6.0%, other countries 5.4%.

In the first half of 2026, the Company achieved sales revenues from one partner in the amount of PLN 0.5 million, representing 33.3% of total revenue from sales. The revenue from sales related to the UPD modules and consumables segment. The Company's key client during this period was a company from Israel.

In H1 2025, the Company generated revenue from sales to a single client in the amount of PLN 3.4 million, representing 58.4% of total revenue from sales. The revenue from sales mainly concerned the sales segment of Delta Printing System laboratory printers and the rental of laboratory equipment. The key client of the Company was the subsidiary XTPL Inc.

Note 27. Information on default on any bank and other loans or a breach of material provisions of bank and other loan agreements where no remedial actions have been taken before the end of the reporting period
No such events occurred in the reporting period.

Note 28. Effect of application of new accounting standards and changes in accounting policy

The accounting policies that were used in preparation of these interim condensed financial statements for the first half of 2026 are consistent with the policies used in preparation of the Company's financial statements for 2025. The same policies were applied for the current and comparative period. Detailed description of the accounting principles adopted by XTPL S.A. and XTPL Group was presented in the annual financial statements for 2025.

Note 29. Types and amounts of changes in estimates presented in prior periods of the present financial year or changes to estimates presented in prior financial years

In the reporting period no changes in estimates were made.

Note 30. Correction of errors from previous periods

In H1 2026, no corrections were made on account of errors from previous periods.

Note 31. Basis of preparation

The interim condensed standalone financial statements of XTPL S.A. cover the 6-month period ended June 30, 2026, and contain comparative data for the 6-month period ended June 30, 2025, and have been prepared under the historical cost convention. The interim condensed standalone financial statements have been prepared on the assumption that the Company will continue in operation for at least a year from the Report Date. As of the date of authorization of these interim condensed standalone financial statements, the Management Board sees no circumstances indicating a threat to the ability of the Company to continue as a going concern in the period described. A detailed description of the assumptions regarding the going concern basis is presented in section 5.16 of this report.

The interim condensed standalone financial statements have been prepared in accordance with the International Accounting Standard ("IAS") 34 Interim Financial Reporting and in accordance with the Finance Minister's Ordinance on current and financial information.

The interim condensed standalone financial statements do not include all the information and disclosures required in the annual financial statements and should be read in conjunction with the annual financial statements for the year ended December 31, 2025.

Note 32. Events occurring after the balance sheet date

Information on significant events after June 30, 2026, is presented in section 5.9.8 of this report.

Note 33. Date of approval of the financial statements for publication

This financial report for the period from January 1, 2026 to June 30, 2026 was approved for publication by the Company's Management Board on September 28, 2026.

4. INTERIM CONDENSED CONSOLIDATED FINANCIAL STATEMENTS

4.1 Interim condensed consolidated statement of financial position

ASSETS	30.06.2026	31.12.2025
PLN '000		
Non-current assets	28,867	30,938
Property, plant and equipment	17,882	18,889
Intangible assets	9,973	11,047
Long-term receivables	1,012	1,002
Current assets	23,146	16,067
Inventories	4,273	4,252
Trade receivables	1,082	3,047
Other receivables	1,201	1,841
Cash and cash equivalents	16,312	6,642
Other assets	278	285
Total assets	52,013	47,005

EQUITY AND LIABILITIES	30.06.2026	31.12.2025
PLN '000		
Total equity	26,130	19,404
Share capital	295	265
Supplementary capital	35,455	38,448
Own shares	- 1	-2
Reserve capital	3,647	3,647
FX differences arising on translation	- 33	-80
Retained earnings	- 13,233	-22,874
Long-term liabilities	15,049	17,119
Long-term financial liabilities	13,390	14,133
Deferred income in respect of grants	1,659	2,986
Short-term liabilities	10,835	10,482
Trade liabilities	1,579	3,634
Short-term financial liabilities	2,758	2,583
Other liabilities	3,202	1,922
Deferred income in respect of grants	3,296	2,343
TOTAL EQUITY AND LIABILITIES	52,013	47,005

4.2 Interim condensed consolidated statement of comprehensive income

INTERIM CONDENSED CONSOLIDATED STATEMENT OF COMPREHENSIVE INCOME	01.01.2026	01.01.2025
	–	–
	30.06.2026	30.06.2025
	PLN'000	PLN'000
Continued operations		
Revenue	3,295	6,003
Revenue from the sale of products and services	1,518	5,132
Revenue from grants	1,777	871
Cost of sales	6,490	9,122
Research and development expenses	4,082	5,873
Cost of finished goods sold	2,408	3,249
Gross profit (loss)	- 3,195	-3,119
Marketing and selling costs	2,237	3,828
General and administrative expenses	5,659	5,673
Other operating income	4	138
Other operating costs	1	3
Operating profit (loss)	- 11,087	-12,485
Financial revenues	35	125
Financial expenses	793	445
Profit/ loss before tax	- 11,846	-12,805
Income tax	–	3
Net profit (loss) on continued operations	- 11,846	-12,808
Discontinued operations		–
Net profit (loss) on discontinued operations	–	–
Net profit (loss) on continued and discontinued operations	- 11,846	-12,808
Profit (loss) attributable to non-controlling interests	–	–
Profit (loss) attributable to shareholders of the parent	-11,846	-12,808
Other comprehensive income	47	-79
Items that can be transferred to profit or loss in subsequent reporting periods	47	-79
FX differences arising on conversion of foreign affiliates	47	-79
Items that will not be transferred to profit or loss in subsequent periods	–	–
Total comprehensive income	- 11,799	-12,887
Total comprehensive income attributable to non-controlling shareholders	–	–
Total comprehensive income attributable to the parent company	- 11,799	-12,887
Net profit (loss) per share (in PLN)	–	–
On continued operations	–	–
Ordinary	-4.03	-4.83
Diluted	-4.03	-4.83
On continued and discontinued operations		
Ordinary	-4.03	-4.83
Diluted	-4.03	-4.83
number of shares to calculate ordinary profit (loss) per share	2,949,877	2,649,877
number of shares to calculate diluted profit (loss) per share	2,949,877	2,649,877

4.3 Interim condensed consolidated statement of changes in equity

INTERIM CONDENSED CONSOLIDATED STATEMENT OF CHANGES IN EQUITY IN EQUITY PLN'000	Share capital	Supplementary capital	Own shares	Reserve capital	FX differences arising on translation	Retained earnings	Non- controlling interests	Total
As at January 1, 2026	265	38,448	- 2	3,647	- 80	- 22,874	—	19,404
Comprehensive income:	-	—	—	—	47	- 11,846	—	- 11,799
Profit (loss) after tax	—	—	—	—	—	- 11,846	—	- 11,846
Other comprehensive income	—	—	—	—	47	—	—	47
Transactions with owners:	30	- 2,993	1	—	—	21,487	—	18,525
Issue of shares	30	18,494	—	—	—	—	—	18,524
Sale of own shares	—	—	1	—	—	—	—	—
Incentive scheme	—	—	—	—	—	—	—	—
Profit distributions	—	- 21,487	—	—	—	21,487	—	—
Value of conversion rights under convertible bonds	—	—	—	—	—	—	—	—
As at June 30, 2026	295	35,455	- 1	3,647	- 33	- 13,233	—	26,130
As at January 1, 2025	265	59,312	- 4	1,510	- 126	- 20,409	—	40,549
Comprehensive income:	-	—	—	—	-79	- 12,808	—	- 12,887
Profit (loss) after tax	—	—	—	—	—	- 12,808	—	- 12,808
Other comprehensive income	—	—	—	—	- 79	—	—	- 79
Transactions with owners:	—	- 20,864	—	—	—	20,864	—	—
Issue of shares	—	—	—	—	—	—	—	—
Sale of own shares	—	—	—	—	—	—	—	—
Incentive scheme	—	—	—	—	—	—	—	—
Profit distributions	—	- 20,864	—	—	—	20,864	—	—
Value of conversion rights under convertible bonds	—	—	—	—	—	—	—	—
As at June 30, 2025	265	38,448	- 4	1,510	- 205	- 12,351	—	- 27,662

4.4 Interim condensed statement of cash flows

	01.01.2026	01.01.2025
INTERIM CONDENSED CONSOLIDATED STATEMENT OF CASH FLOWS	—	—
	30.06.2026	30.06.2025
	PLN'000	PLN'000
Cash flows from operating activities		
Profit (loss) before tax	- 11,846	- 12,805
Total adjustments:	6,124	1,833
Depreciation/amortization	3,493	2,779
FX gains (losses)	338	- 252
Interest and profit distributions (dividends)	591	195
Profit (loss) on investing activities	- 2	- 136
Change in the balance of provisions	275	171
Change in the balance of inventories	- 21	185
Change in the balance of receivables	2,595	949
Change in short-term liabilities, except for bank and other loans	- 778	- 1,120
Change in other assets	7	- 67
Change in the balance of grants to be settled	- 374	- 871
Incentive scheme valuation	—	—
Income tax paid	—	—
Other adjustments	—	—
Total cash flows from operating activities	- 5,722	- 10,973
Cash flows from investing activities		
Inflows	43	4
Disposal of tangible and intangible assets	2	4
Repayment of long-term loans	—	—
Interest on financial assets	41	—
Outflows	1,412	440
Acquisition of tangible and intangible assets	1,412	440
Acquisition of financial assets	—	—
Long-term loans granted	—	—
Other investment outflows	—	—
Total cash flows from investing activities	- 1,369	- 436
Cash flows from financing activities		
Inflows	18,556	107
Contributions to capital	18,524	—
Bank and other loans	31	107
Other financial inflows	1	—
Outflows	1,795	589
Repayment of bank and other loans	—	—
Finance lease payments	1,163	297
Interest	632	292
Total cash flows from financing activities	16,761	- 482
Total net cash flows	9,670	- 11,891
Change in cash and cash equivalents:	9,670	- 11,859
— change in cash due to FX differences	34	32
Cash and cash equivalents at the beginning of the period	6,642	27,686
Cash and cash equivalents at the end of the period, including:	16,312	15,795
— restricted cash	1	131

4.5 Notes

Note 1. Intangible assets

INTANGIBLE ASSETS	figures in PLN thousand	30.06.2026	31.12.2025
Acquired concessions, patents, licenses and similar rights		–	–
Intellectual property rights		–	–
other intangible assets		803	1,000
Completed development		8,011	9,179
In-process development expenditure		1,159	867
Total (net)		9,973	11,047
Accumulated amortization		6,599	5,213
Total (gross)		16,572	16,260

All intangible assets are the property of the Group; none of these assets are used based on any rental, lease or a similar contract. The intangible assets are not used as collateral by the Group. As at June 30, 2026, the Group did not have any agreements whereby it would be required to purchase any intangible assets. In 2026 and 2025, no impairment charges were posted for intangible assets.

As at June 30, 2026, under the item “Other intangible assets”, the Group presents the net value of licenses held.

As at June 30, 2026, under “Completed development”, the Group presents expenditure on completed development relating to:

- Development of a demonstration prototype of a laboratory printer: net amount PLN 1,107 thousand;
- R&D OLED hardware: net amount PLN 1,611 thousand;
- R&D 3D PRINT hardware: net amount PLN 2,273 thousand;
- UPD industrial printhead: net amount PLN 3,020 thousand.

Under the item “In-process development expenditure” as of June 30, 2026, the Group presents expenditure on development projects that have not yet been brought into use and which relate to:

- development costs related to copper ink in the gross amount of PLN 730 thousand;
- development costs related to extending the service life of nozzles used in DPS printers and UPD modules in the gross amount of PLN 429 thousand.

The table below presents the expenditures incurred on development during production in the period from January 1, 2026 to June 30, 2026, broken down by cost types.

	PLN '000
In-process development expenditure, including	
Salaries	155
External services	58
Materials	78
Other	–
Impairment allowances on capitalized expenditure	–
Total	292

Note 2. Property, plant and equipment and significant acquisitions of property, plant and equipment

PROPERTY, PLANT AND EQUIPMENT	figures in PLN thousand	30.06.2026	31.12.2025
Tangible assets, including:		17,330	18,448
Buildings, premises, rights to premises and civil and water engineering structures		14,161	15,059
Technical equipment and machines		190	257
Vehicles		120	81
Other tangible assets		2,859	3,051
Tangible assets under construction		552	441
Property, plant and equipment, net		17,882	18,889
Accumulated amortization		12,065	10,127
Property, plant and equipment, gross		29,948	29,016

Property, plant and equipment under construction consists of expenditure incurred on the UPD Pro head in the amount of PLN 254 thousand and the ODRA system in the amount of PLN 268 thousand.

Other property, plant and equipment consist of laboratory and measuring equipment (Group 8) used by employees of the R&D departments.

No tangible assets are used as collateral. In 2026 and 2025, no impairment losses were recognized for tangible assets.

As at June 30, 2026, the Group uses property, plant and equipment under rental and leasing agreements in the net amount of PLN 14,838 thousand.

TANGIBLE ASSETS LEASED	30.06.2026			31.12.2025		
	Gross value	Depreciation	Net value	Gross value	Depreciation	Net value
Buildings, premises, rights to premises and civil and water engineering structures	15,514	- 1,383	14,132	17,426	-2,432	14,994
technical equipment and machines	281	- 140	140	281	-140	140
other tangible assets	560	- 175	385	2,239	-1,668	571
vehicles	220	- 39	181	241	-160	81
Total	16,575	- 1,738	14,838	20,186	-4,400	15,786

The table below presents the acquisition of material items of property, plant and equipment.

SIGNIFICANT INCREASES IN PROPERTY, PLANT AND EQUIPMENT, AND LEASES	figures in PLN thousand	01.01.2026 - 30.06.2026	01.01.2025 - 31.12.2025
Other laboratory equipment		—	34
Office and laboratory space for rent, ul. Legnicka 48E		295	10,864
Nanoparticle size analyzer		—	200
Fume hoods		—	154
Precision scales		—	16
Demineralizers		—	21
Double-beam spectrophotometer		—	45
Chilled water unit		—	30
Homogenizator ARV-310P		—	84
Laboport vacuum system		—	19
XTPL DPS-ODR7 printer		172	—
— Hydra multihead		386	—
Mazda CX-5 25 passenger car – lease		78	—
Microforge nozzle forming station		46	—
Micropipette beveler		12	—
Total significant acquisitions		989	11,468

Note 3. Significant liabilities on account of purchase of tangible assets

As at June 30, 2026, the Group did not have any agreements whereby it would be required to purchase any tangible assets.

The Group has liabilities arising from the rental and leasing of property, plant and equipment in the amount of PLN 15,814 thousand (including short-term liabilities of PLN 2,423 thousand and long-term liabilities of PLN 13,390 thousand).

The maturity period of liabilities is presented in the table below.

Year	Repayment period				short term	long term	Total
	up to 1 year	1 year to 3 years	3 to 5 years	above 5 years			
2026	2,423	4,877	5,633	2,880	2,423	13,390	15,814

Note 4 Changes in the classification of financial assets as a result of a change in the purpose or use of these assets

In the reporting period no changes were made in the classification of financial assets.

Note 5. Impairment allowance for financial assets, tangible assets, intangible assets or other assets and reversal of the impairment allowance

In the period presented, there were no impairment allowances on financial assets, property, plant and equipment, intangible assets or other assets or any reversal of such impairment allowances.

Note 6. Long-term receivables

Long-term receivables	figures in PLN thousand	30.06.2026	31.12.2025
Loans granted		–	–
Security deposits		1,012	1,002
Shares		–	–
For equipment used under rental agreements		–	–
Total long-term receivables		1,012	1,002

As at June 30, 2026, the Group presents PLN 1,012 thousand under “Deposits,” comprising PLN 982 thousand related to rental of office and laboratory space and PLN 30 thousand representing a security deposit from a client.

Note 7. Write-down of inventories to their net recoverable amount and reversal of the write-down

In the Reporting Period, no write-down (impairment allowance) of inventories was created or reversed.

Note 8. Change in the balance of provisions

CHANGE IN THE BALANCE OF PROVISIONS	figures in PLN thousand	01.01.2026 - 30.06.2026	01.01.2025 - 31.12.2025
Balance at the beginning of the period		481	398
increased/ created		275	83
utilization		–	–
release		–	–
Balance at the end of the period		756	481

The change in provisions presented in the table above relates to provisions created for unused annual leaves by Group employees. The above provisions are presented in the statement of financial position under other liabilities.

Note 9. Share capital

On March 30, 2026, the Management Board of the Issuer submitted a statement determining the amount of the Company's share capital in the Articles of Association, in such way that the Company's share capital amounts to PLN 294,987.70 (two hundred ninety-four thousand nine hundred and eighty-seven zloty and 70/100) and is divided into 2,949,877 ordinary bearer shares with a nominal value of PLN 0.10 (ten groszy) each, including:

REF.	number of shares	series
1	670,000	A
2	300,000	B
3	30,000	C
4	198,570	D
5	19,210	E
6	19,210	F
7	68,720	G
8	68,720	H
9	10,310	I
10	5,150	J
11	10,310	K
12	140,020	L
13	155,000	M
14	47,000	N
15	41,400	O
16	42,602	P
17	78,000	S
18	125,000	T
19	45,655	U
20	275,000	V
21	300,000	X
22	300,000	Y

Below, the Group presents information summarizing the public offering (in the form of a private placement) of series Y ordinary bearer shares issued pursuant to resolution No. 03/03/2026 of the Extraordinary General Meeting of the Company of March 9, 2026 on increasing the Company's share capital by issuing series Y ordinary bearer shares (fully disapplying shareholders' preemption rights), amending the Company's Articles of Association and applying for the admission and introduction of those shares to trading on the regulated market ("Series Y Shares"):

1. Dates of commencement and completion of the subscription for the Series Y Shares: Subscription agreements for Series Y Shares were concluded on March 16–20, 2026.

2. Date of allotment of the Series Y Shares: The subscription of Series Y Shares was carried out in the form of a private placement, so no shares allocations were made within the meaning of Article 434 of the Commercial Companies Code. On March 25, 2026, the Management Board of the Company submitted a statement regarding the determination of the Company's share capital in the Articles of Association.
3. Number of Series Y Shares subscribed for: The private placement for Series Y Shares included no fewer than 1 and no more than 300,000 Series Y Shares.
4. Reduction rates in individual tranches: The Series Y Shares were subscribed for by investors through a private subscription; therefore, no allocation reduction was necessary. The subscription of the Series Y Shares was not divided into tranches.
5. Number of Series Y Shares for which subscription offers were accepted: A total of 300,000 Series Y Shares were subscribed for and accepted in the private placement.
6. Number of Series Y Shares taken up in the completed private placement: 300,000 Series Y Shares were taken up in the private placement.
7. Price at which the Series Y Shares were taken up:
The issue price per Series Y share was PLN 65 (sixty-five zloty) per Series Y share. The total issue price of all Series Y shares subscribed by investors amounted to PLN 19,500,000 (nineteen million five hundred thousand zloty).
8. Number of investors who entered into subscription agreements for Series Y Shares: Subscription agreements for Series Y Shares were executed with a total of 27 investors.
9. Names of the sub-underwriters who took up Shares under the sub-underwriting agreements, specifying the number of Series Y Shares they subscribed for, together with the actual price per Series Y Share (issue or sale price, net of the fee for subscribing to the financial instrument unit under the sub-underwriting agreement, paid by the sub-underwriter): No Series Y Shares were taken up by sub-underwriters.
10. Value of the completed placement or sale: The value of the Series Y share subscription (defined as the product of the number of Series Y shares subscribed for and their issue price) amounted to PLN 19,500,000 (nineteen million five hundred thousand zloty).
11. Total costs recognized as expenses of the Series Y Share issuance: As of the date of this report, the total estimated costs recognized as expenses of the Series Y Share issuance amounted to PLN 975,922.00, including:
 - a) preparation and execution of the offer: PLN 975,922.00;
 - b) remuneration of underwriters: not applicable;
 - c) preparation of the prospectus, including advice: not applicable;
 - d) offer promotion: not applicable.
12. The average estimated cost of conducting the subscription per Series Y Share amounts to: PLN 3.25.
13. Method of payment for the subscribed Series Y Shares:
The Series Y Shares were paid for in cash.
Series Y shares were admitted to trading on the Warsaw Stock Exchange (GPW) on April 17, 2026, under ISIN code PLXTPL000018.

Note 10. Transfers between individual fair value hierarchy levels in respect of financial instruments

In the reporting period no transfers took place between individual fair value hierarchy levels in respect of financial instruments.

The Group does not identify financial instruments classified within Level 1 or Level 2 of the fair value hierarchy.

Note 11. Fair value of the individual classes financial assets and liabilities

	Category	Book value		Fair value	
		30.06.2026	31.12.2025	30.06.2026	31.12.2025
Financial assets					
Loans granted	WwgZK	–	–	–	–
Trade receivables	WwgZK	1,082	3,047	1,082	3,047
Equipment lease receivables	according to IFRS 16	–	–	–	–
Other receivables	WwgZK	2,213	1,841	2,213	1,841
Cash and cash equivalents	WwgZK	16,312	6,642	16,312	6,642
Total		19,607	11,530	19,607	11,530
Financial liabilities					
Interest bearing bank and other loans	PZFwgZK	335	304	335	304
Bond liabilities	WwWGpWF	–	–	–	–
Lease liabilities	according to IFRS 16	15,814	16,413	15,814	16,413
Trade liabilities	PZFwgZK	1,579	3,634	1,579	3,634
Other liabilities	PZFwgZK	1,591	1,442	1,591	1,442
Total		19,319	21,792	19,319	21,792

Abbreviations used:

WwgZK – Measured at amortized cost

PZFwgZK – Other liabilities measured at amortized cost

WwWGPWF – Financial assets/ liabilities measured at fair value through profit or loss

Fair value of financial instruments that the Group held as at June 30, 2026 and December 31, 2025 was not materially different from the values presented in the financial statements for the respective years:

- with regard to short-term instruments, the potential effect of the discount is not material;
- the instruments relate to the transactions concluded on market terms.

Note 12. Explanations to the statement of cash flows

Presented below are explanations to selected items of the statement of cash flows.

	figures in PLN thousand	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
PBT presented in the statement of comprehensive income		- 11,846	-12,805
PBT presented in the statement of cash flows		- 11,846	-12,805

INTEREST AND DIVIDENDS IN THE STATEMENT OF CASH FLOWS	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Realized interest on financing activities	632	214
Realized interest on investing activities	- 41	-19
Unrealized interest on financing activities	–	–
Unrealized interest on investing activities	–	–
Total interest and dividends:	591	195

CHANGE IN THE BALANCE OF RECEIVABLES	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Change in the balance of trade receivables	1,965	961
Other receivables	630	-12
Total change in the balance of receivables:	2,595	949

CHANGE IN THE BALANCE OF LIABILITIES	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Change in the balance of trade liabilities	- 2,055	-1,405
Other liabilities	1,277	285
Total change in the balance of liabilities:	- 778	-1,120

Cash and cash equivalents at the end of the period	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Statement of cash flows	16,312	15,795
Statement of financial position	16,312	15,827

Inflow from grants	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
– to operations	1,434	–
– to assets	–	–
– advance payments not settled/ (settled)	–	–
Total grant proceeds	1,434	–

The difference between the balance of cash presented in the statement of financial position as at June 30, 2026 and the value of cash presented in the statement of cash flows results from the exchange rate differences relating to the valuation of cash held in the bank accounts.

Proceeds from grants mainly comprise funds received under the STEP and Ultrasens grant projects.

Note 13. Revenue

REVENUE	figures in PLN thousand	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Research and development revenue		270	531
Revenue from the sale of products		1,248	4,602
Revenue from sales – leases		–	–
Revenue from grants		1,777	871
Total Revenue		3,295	6,003

During the reporting period, the Parent Company recognized grant revenue of PLN 1,777 thousand.

In accordance with IAS 20, grants to assets are also recognised in the liabilities of the statement of financial position at the balance sheet date. Grants to depreciable assets will be recognized in the Group's profit or loss over the individual periods in proportion to the recognition of depreciation on those assets.

Note 14. Operating costs

OPERATING COSTS	figures in PLN thousand	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Depreciation/ amortization, including		3,493	2,779
– depreciation of tangible assets		2,107	1,729
– amortization of intangible assets		1,386	1,050
Use of raw materials and consumables		1,470	2,368
External services		2,860	4,743
Cost of employee benefits		6,492	8,297
Taxes and charges		162	246
Other costs by type		201	486
Value of goods and materials sold		–	–
Total costs by type, including:		14,678	18,918
Items reported as research and development costs		4,082	5,873
Items reported as cost of finished goods sold		2,408	3,249
Marketing and selling costs		2,237	3,828
Items reported as general and administrative expenses		5,659	5,673
Change in product inventories		–	-101
Cost of producing services for internal needs of the entity		292	397

Note 15. Related party transactions

01.01.2026 - 30.06.2026	figure s in PLN thous and	To key management personnel*	To joint ventures	To other related entities **	To associates
Purchase of services		–	–	–	–
Loans granted		–	–	–	–
Revenue from the sale of products		–	–	–	–
Revenue from the sale of services		–	–	–	–
Cost of products sold		–	–	–	–
Financial expenses – interest on loans		–	–	–	–

01.01.2025 - 30.06.2025	figure s in PLN thous and	To key management personnel*	To joint ventures	To other related entities **	To associates
Purchase of services		–	–	–	–
Loans granted		–	–	–	–
Revenue from the sale of products		–	–	–	–
Revenue from the sale of services		–	–	–	–
Cost of products sold		–	–	–	–
Financial expenses – interest on loans		–	–	–	–

* the item includes persons who have the authority and responsibility for planning, managing and controlling the company's activities

** the item includes entities linked through key management

Terms of related party transactions

Sales to and purchases from related parties are made on an arm's length basis. Any overdue liabilities/receivables existing at the end of the period are interest-free and settled on cash or non-cash basis. The Group does not charge late interest from other related entities. Receivables from or liabilities to related parties are not covered by any guarantees given or received. They are not secured in any other way either.

Note 16. Deferred tax

Deferred income tax assets due to negative temporary differences	Statement of financial position as at		Impact on the statement of comprehensive income
PLN '000	30.06.2026	31.12.2025	01.01.2026 - 30.06.2026
Due to differences between the carrying amount and the tax value:			
Accruals for unused annual leaves	3	–	–
Provision for salaries	–	–	–
Provision for the cost external services	–	–	–
Provision for extra social security costs	–	–	–
Leased tangible assets	–	–	–
Exchange differences on translation	–	–	–
Total deferred tax assets	3	–	–
Offset against the deferred tax liability	3	–	–
Net deferred tax assets	–	–	–

Deferred tax liability caused by positive temporary differences	Statement of financial position as at		Impact on the statement of comprehensive income
PLN '000	30.06.2026	31.12.2025	01.01.2026 - 30.06.2026
Due to differences between the carrying amount and the tax value:			
Interest on loans and deposits	3	–	–
Leased tangible assets	–	–	–
Total deferred tax liability	3	–	–
Offset against the deferred tax assets	3	–	–
Net deferred tax liability	–	–	–

Negative temporary differences and tax losses for which no deferred tax asset was recognized in the statement of financial position:	Basis for generating the asset at the end of the period June 30, 2026	Basis for generating the asset at the end of the period December 31, 2025	Date of expiry of negative temporary differences, tax losses
In respect of:			
Salaries	41	305	
Accruals for unused annual leaves	495	479	
Provision for the cost external services	213	258	
Leased tangible assets	1,035	674	
Provision for extra social security costs	87	–	

Exchange differences on translation	45	—	
Tax losses	46,313	41,208	2026/2031

Note 17. Objectives and rules of financial risk management

The Group is exposed to risk in each area of its operations. With understanding of the threats that originate through the Company's exposure to risk and the rules for managing these threats the Group can run its operations more effectively. Financial risk management includes the processes of identification, assessment, measurement and management of this risk. The main financial risks to which the Group is exposed include:

- Market risks:
- The risk of changes in market prices (price risk)
- The risk of changes in foreign exchange rates (currency risk)
- The risk of changes in interest rates (interest rate risk)
- Liquidity risk
- Credit risk.

The risk management process is supported by appropriate policies, organisational structure and procedures.

MARKET RISK

The Group actively manages the market risk to which it is exposed. The objectives of the market risk management process are to:

- limit the volatility of pre-tax profit/loss
- increase the probability of achievement of the budget plan
- maintain the Group in good financial condition
- support the strategic decision-making process in the area of investment activity, taking into account the sources of investment financing

All market risk management objectives should be considered jointly, and their achievement is primarily dependent on the Group's internal situation and market conditions.

PRICE RISK

In the period from January to June 2026, the Group did not invest in any debt instruments and, therefore, is not exposed to any price risk.

CURRENCY RISK

The Group is exposed to currency risk in respect of the transactions it concludes. Such risk arises when the Group makes purchases in currencies other than the valuation currency, mainly in USD and EUR.

Part of the Group's settlements is denominated in foreign currencies. As at June 30, 2026, the Group has assets denominated in foreign currencies, which include trade receivables. The value of the liabilities in foreign currencies as at the balance sheet date relates to trade liabilities. Therefore, there is a risk related to the negative impact of FX changes on the financial results achieved by the Group. In order to mitigate the possible effects of exchange rate fluctuations, the Group monitors the current exchange rates on an ongoing basis.

INTEREST RATE RISK

Deposit transactions are made with institutions with a strong and stable market position. The instruments used – short-term, fixed-rate transactions – ensure full security.

Consequently, the recent interest rate hikes do not affect the Group's operations. Consequently, the Group did not apply interest rate hedges, considering that interest rate risk is not significant for its business.

LIQUIDITY RISK

The Group monitors the risk of a lack of funds using the periodic liquidity planning tool. This tool takes into account the maturity dates of both investments and financial assets (e.g. accounts receivable, other financial assets) and projected cash flows from operating activities.

The Group seeks to maintain a balance between continuity and flexibility of financing by using different sources of financing, such as finance leases.

The Group is exposed to financing risk due to the possibility that it in the future it will not receive sufficient cash to fund commercialization of its research and development projects.

In the reporting period, an overdraft of PLN 600 thousand was available to the Parent Company. During the reporting period, the Parent Company used the facility occasionally and for a short period.

Santander Bank Polska: limit of PLN 200 thousand until April 13, 2027;

ING Bank Śląski: limit of PLN 400 thousand until March 31, 2027;

CREDIT RISK

In order to mitigate the credit risk related to cash and cash equivalents deposited in banks, loans granted, deposits paid in respect of rental contracts and performance security as well as trade credit, the Group:

- cooperates with banks and financial institutions with a known financial position and established reputation
- analyzes the financial position of its counterparties based on publicly available data as well as through business intelligence agencies
- in the event of a risk of customer insolvency, the Group secures its proceeds with bank guarantees or corporate guarantees.

Note 18. Material settlements on account of court cases

At the reporting date there are no court proceedings pending whose value would be considered material. Furthermore, in the period covered by the interim report no material settlements were made on account of court cases.

Note 19. Information about changes in the economic position and operating conditions which might have a material impact on the fair value of the financial assets and liabilities, whether those assets and liabilities are recognized at fair value or at adjusted purchase price (amortized cost)

In the period from January 1, 2026 to June 30, 2026, no significant changes were identified in the economic position or operating conditions which would have a material impact on the fair value of the Group's financial assets and liabilities.

Note 20. Information about changes in contingent liabilities and contingent assets and non-disclosed liabilities arising from contracts in relation to the last reporting period

Contingent liabilities granted by the Parent Company were in the form of promissory notes together with promissory note declarations to secure the contracts for co-financing projects financed by the EU.

At the Balance Sheet Date and until the date of approval of the financial statements for publication, no events occurred that could result in materialisation of the above contingent liabilities. As at the date of approval of the financial statements there were no undisclosed liabilities resulting from any agreements of material value. In addition, the Entity issues promissory notes to secure its liabilities under lease agreements up to the amount of such liabilities.

The increase in the value of contingent liabilities as of June 30, 2026, by the amount of PLN 505 thousand is related to the receipt of a grant tranche under the project FENG.05.01-IP.01-001P/25.

CONTINGENT LIABILITIES	30.06.2026	31.12.2025
Promissory notes	14,638	14,133
Total contingent liabilities	14,638	14,133

Note 21. Incentive scheme

In the Reporting Period, the Group did not grant any instruments or recognize in the interim condensed statement of comprehensive income any cost of the incentive scheme for employees and collaborators based on the Parent Company's shares.

Note 22. Information about seasonality of business and cycles

The Group's activity is not subject to seasonality or business cycles.

Note 23. Extraordinary factors which occurred in the reporting period with an indication of their impact on the financial statements

In the reporting period, no extraordinary events occurred that would affect the interim condensed financial statements.

Note 24. Information on issue, redemption and repayment of debt and equity securities

In the first half of 2026, the Group decided to initiate actions aimed at securing funding for the Company based on raising funds through the issuance of new shares (ESPI Current Report No. 3/2026 of February 9, 2026). For more information on the issuance of new shares, see section Note 9 Share capital and section 5.9.2 Issuance of securities this report.

Note 25. Dividend paid or declared, in total and per share, with a division into ordinary and preference shares

In the reporting period the Parent Company did not pay or declare any dividends.

Note 26. Operating segments

The Group's reporting segments are based on product groups.

As at the Reporting Date, the Group distinguished three product groups:

- Delta Printing System laboratory printers and UPD modules
- silver-based conductive nanoinks;
- research services related to printing on client-supplied substrates in the manner specified by the client, in order to demonstrate the suitability of the XTPL technology to solve technological production problems (Proof of Concept).

SALES REVENUE BY SEGMENTS	01.01.2026 – 30.06.2026	01.01.2025 – 30.06.2025
Sale and lease of printers	1,043	4,051
Nanoinks and other consumables	205	551
Leasing services	–	–
Research and development services	270	531
TOTAL	1,518	5,132

As at June 30, 2026, the Group presents in its statement of financial position PLN 1,017 thousand in trade receivables and PLN 1,391 thousand representing costs incurred on work in progress. The above amounts relate to the segment of laboratory printers – the Delta Printing System – the UPD modules.

In its statement of financial position, the Group presents PLN 65 thousand in respect of trade receivables and PLN 53 thousand relating to expenditure on work in progress. The above amounts relate to the inks and consumables segment.

Revenue from sales recognized by the Group in the first half of 2026, in the amount of PLN 1,518 thousand, relates to transactions concluded with foreign clients.

The following countries had the largest percentage share in sales: 33.8% Israel, Taiwan 18.7%, China 14.4%, Japan 10.5%, USA 9.0%, Germany 4.3%, Portugal 2.4%, UK 1.5%, Romania 1.4%, other countries 3.9%.

As at December 31, 2025, the Group presented in its statement of financial position PLN 2,888 thousand in trade receivables and PLN 1,827 thousand representing costs incurred on work in progress. The above amounts relate to the segment of laboratory printers – the Delta Printing System, and UPD modules.

As at December 31, 2025, the Group shows in the statement of financial position PLN 156 thousand concerning trade receivables in the inks and consumables segment.

As at December 31, 2025, the Group shows in the statement of financial position PLN 3 thousand concerning trade receivables in the R&D segment.

Revenue from sales recognized by the Group in the first half of 2025, in the amount of PLN 5,069 thousand, relates to transactions concluded with foreign clients (representing 98.8%). In the first half of 2025, the Group recognized PLN 63 thousand from sales transactions with domestic entities (representing 1.2%).

The following countries had the largest percentage share in sales: USA 55.1%, China 17.4%, UK 14.5%, Germany 6.8%, other countries 6.1%.

In the first half of 2026, the Group achieved sales revenues from one partner in the amount of PLN 0.5 million, representing 33.3% of total revenue from sales. The revenue from sales related to the UPD modules and consumables segment. The Group's key client during this period was a company from Israel.

In H1 2025, the Group generated revenue from sales to a single client in the amount of PLN 0.8 million, representing 16.9% of total revenue from sales. The sales revenues mainly concerned the sales segment of Delta Printing System laboratory printers and consumables. The Group's key client was a company from the southwestern part of the United States.

Note 27. Information on default on any bank and other loans or a breach of material provisions of bank and other loan agreements where no remedial actions have been taken before the end of the reporting period

No such events occurred in the reporting period.

Note 28. Effect of application of new accounting standards and changes in accounting policy

The accounting policies that were used in preparation of these interim condensed consolidated financial statements for the first quarter of 2026 are consistent with the policies used in preparation of the Company's financial statements for 2025. The same policies were applied for the current and comparative period. Detailed description of the accounting principles adopted by XTPL S.A. and XTPL Group was presented in the annual financial statements for 2025.

Note 29. Types and amounts of changes in estimates presented in prior interim periods of the present financial year or changes to estimates presented in prior financial years

In the reporting period no changes in estimates were made.

Note 30. Correction of errors from previous periods

In H1 2026, no corrections were made on account of errors from previous periods.

Note 31. Basis of preparation

The interim condensed consolidated financial statements of the XTPL Group cover the 6-month period ended June 30, 2026, and contain comparative data for the 6-month period ended June 30, 2025, and have been prepared under the historical cost convention. The interim condensed consolidated financial statements have been prepared on the assumption that the Group and its subsidiaries will continue in operation for at least a year from the Report Date. As of the date of authorization of these interim condensed consolidated financial statements, the Management Board of the Parent Company sees no circumstances indicating a threat to the ability of the Group to continue as a going concern in the period described. A detailed description of the assumptions regarding the going concern basis is presented in section 5.16 of this report.

The interim condensed consolidated financial statements have been prepared in accordance with the International Accounting Standard ("IAS") 34 Interim Financial Reporting and in accordance with the Finance Minister's Ordinance on current and financial information.

The interim condensed consolidated financial statements do not include all the information and disclosures required in the annual financial statements and should be read in conjunction with the annual financial statements for the year ended December 31, 2025.

Note 32. Events occurring after the balance sheet date

Information on significant events after June 30, 2026, is presented in section 5.9.8 of this report.

Note 33. Date of approval of the financial statements for publication

This financial report for the period from January 1, 2026 to June 30, 2026 was approved for publication by the Parent Company's Management Board on September 28, 2026.

Filip Granek
CEO

Jacek Olszański
Management Board Member

Signature of the person responsible for keeping the books of account.

Edward Czuchajewski
Chief Accountant

5. MANAGEMENT REPORT ON THE OPERATIONS OF THE ISSUER AND THE GROUP AND ON THE BASIS OF PREPARATION OF THE INTERIM CONDENSED STANDALONE AND CONSOLIDATED FINANCIAL STATEMENTS

5.1 Key information about the Issuer

Business name:	XTPL Spółka Akcyjna
Registered Office:	Wroclaw, Poland
Address:	Legnicka 48E, 54-202 Wroclaw, Poland
Country	Poland
KRS:	0000619674
NIP:	9512394886
REGON:	361898062
Registry Court:	District Court for Wrocław-Fabryczna, VI Commercial Division of the National Court Register
Place of registration:	Poland
Share capital:	PLN 294,987.70, paid up in full
Phone number:	+48 71 707 22 04
Internet address:	www.xtpl.com
E-mail:	investors@xtpl.com

The Company has the status of a public (listed) company. Since February 20, 2019, its shares have been listed on the regulated (parallel) market operated by the Warsaw Stock Exchange.

WSE Ticker	XTP
ISIN	PLXTPL000018
Number of shares	2,949,877
Free float	44.62%
Indexes	WIG, WIGTECH, INNOVATOR, WIGtechTR, WIG-Poland, GPWB-CENTR and CEEplus.

Since March 2020, the Company has also been listed on the Open Market at Deutsche Börse in Frankfurt (FRA ticker: 5C8). As regards financial reporting, the Group and the Company use IASs/ IFRSs. The Group's and the Company's financial year is from January 1 to December 31.

5.2 Company history

Year	Milestone	Strategic significance
2015-2016	Establishment of XTPL in Wrocław and initial development of the UPD concept	Establishment of the scientific and engineering foundations for additive printing with sub-micrometer resolution. Definition of the company's long-term strategic direction in high-precision microelectronics manufacturing.
2017-2018	Initial validation of the deposition principle and first proprietary nozzle designs and ink formulations	Feasibility of ultra-precise additive deposition was demonstrated, confirming its differentiation from conventional printing and lithography. XTPL established its position as an R&D organization dedicated to advanced technologies.

Year	Milestone	Strategic significance
2017	IPO and debut on the NewConnect market	Entry into an ecosystem enabling the financing of a tech start-up.
2019	Debut on the regulated (parallel) market operated by the Warsaw Stock Exchange	Access to a broad market enabling the financing of business development and R&D activities.
2020	First sales transaction of a proprietary product – conductive ink based on silver nanoparticles	Delivery completed for one of the partners operating in XTPL's first commercialized application field within the display sector, establishing the Company as a commercial supplier.
2020	Market launch of the Delta Printing System (DPS)	The company's first commercial hardware product. Enables global research institutions to deploy UPD technology for microfabrication research and prototyping. Provides early revenues and global recognition.
2020-2021	First sales and deployments of DPS systems across Europe, Asia, and North America; growing number of scientific publications referencing XTPL materials and processes	Creates a distributed ecosystem of researchers and early adopters. Provides external technology validation and accelerates the discovery of new applications. Expands commercial reach.
2021-2022	Strategic focus on industrial applications in displays, semiconductor packaging, and HDI electronics	Introduces a structured client engagement model (feasibility – validation – prototype – industrial implementation). Strengthens focus on high-value industrial markets.
2022	Agreement with NASDAQ-listed Israeli company Nano Dimension Ltd. for the development of a special ink formulation for the printed circuit board (PCB) and Additively Manufactured Electronics (AME) markets.	Strengthens XTPL's position in the market as a provider of proprietary solutions in the area of High Performance Materials.
2022	Publication of research results on UPD technology in Scientific Reports, demonstrating the ability to print with one-micrometer accuracy at various stages of the process and on complex topographies.	Expert-verified proof of performance at an industrial level in the context of microelectronics. This increases the Company's credibility among leading manufacturers and equipment integrators.
2022	Sale of the first UPD module for industrial integration into a prototype industrial device for semiconductor manufacturing applications to a partner from Taiwan.	The transition to close cooperation between the Company and the Partner, focused on the development and industrial deployment of a device on the production lines of a leading global semiconductor component manufacturer in Taiwan, confirms the attractiveness of the Company's technological solution and the commercial potential of XTPL's technology within the business line of printing modules for industrial integration.

Year	Milestone	Strategic significance
2023	Publications in Advanced Functional Materials and ACS Omega demonstrating the significance of UPD technology for OFET transistors and flexible QLEDs.	Expands the technological significance of the technology beyond displays to semiconductors and printed optoelectronics. Strengthens the Company's references in materials and processes.
2023-2024	Progression of multiple industrial projects to advanced validation stages (Korea, China, Taiwan, USA).	Confirms demand across different regions. Demonstrates applicability in display repair, advanced packaging, and high-density interconnects. Prepares the technology for industrial-scale deployment.
2024	Establishment of the XTPL Demo Center in Boston.	A dedicated center for customers in North America. Increases support capabilities for research and development institutions and industrial partners. Expands the Company's global commercial reach.
2025	First industrial deployment: order for six UPD modules from a major global display manufacturer (revenue of more than USD 20 billion).	Marks the transition from an R&D-focused business to industrial deployments. Provides a key reference installation, enabling the acceleration of subsequent industrial projects.
2025	Expansion of the industrial project portfolio to eleven active projects in major electronics markets.	Strengthens the pace of industrial development and demonstrates growing customer interest. Lays the foundation for scaling operations across multiple locations and production lines.
2025	Sale of the Delta Printing System to a defence contractor in the USA	Opens up a significant, specialized market with high growth potential in the context of the geopolitical situation.
2026	Establishment of a strategic partnership with Manz Asia in Taiwan.	Entry into a semiconductor innovation hub in Taiwan and expansion of the distribution network in Taiwan and India.
2026	First sale of the ODRA system to an industrial client serving the semiconductor sector in the defense and AI industries in the U.S.	It fills the gap between laboratory DPS (Delta Printing System) devices and industrial UPD modules. The standalone system is designed for High-Mix, Low-Volume (HMLV) industrial manufacturing, i.e., diversified production in small batches.
2026	Framework order for 10 UPD modules for advanced display (FPD) technology, as part of the continuation of the first industrial deployment of XTPL's technology.	Confirms the continuation of cooperation with a global display manufacturer as part of a multi-year deployment project.
2016–present	Consolidation of XTPL's position as a provider of precision additive technology in the display, semiconductor, printed circuit board, and flexible electronics industries.	Prepares XTPL for further development. Integrates hardware, materials, and process know-how into a coherent platform tailored to long-term industry trends.

5.3 Description of activities

XTPL is a deep tech company engaged in the commercialization of Ultra-Precise Dispensing (UPD) technology – a proprietary additive nanoprinting platform that enables the micrometer-scale deposition of functional materials using ultra-high viscosity pastes and inks. The Company addresses a critical bottleneck in next-generation electronics manufacturing, where conventional methods of photolithography, wire bonding, and droplet-based printing reach fundamental technical, economic, and sustainability limitations. XTPL technology enables maskless, selective, three-dimensional material deposition on complex substrates, paving the way for novel devices in displays, advanced semiconductor packaging, and micro-LED manufacturing.

Technology: Ultra-Precise Dispensing is a patented, pressure-driven process that enables printing feature sizes down to 1 μm while handling materials with viscosities up to >2,500,000 cP and metal contents of 85–87%. The process operates without the need for cleanrooms, electric fields, or photomasks, and enables 3D printing on steps, grooves, edges, and other heterogeneous or curved surfaces.

Value Proposition: XTPL combines sub-10 μm precision, exceptional material versatility, and true 3D capabilities into a single, production-proven additive process. Clients benefit from lower capital expenditures compared to photolithography, an 80–90% reduction in material waste, faster development cycles, and the ability to perform localized repairs and enhancements that are impossible using conventional methods.

5.4 Issuer's governing bodies

Management Board

As at the Balance Sheet Date, the Management Board performed its duties in the following composition:

- Filip Granek, PhD – CEO
- Jacek Olszański – Management Board Member.

On June 30, 2026, in connection with the Annual General Meeting of the Company, which approved the financial statements of the Issuer and the Issuer's group for the fiscal year 2025, the terms of office of the existing Members of the Management Board expired.

In light of the above, on June 30, 2026, the Company's Supervisory Board appointed the Management Board for a new term of office, composed of the following members:

- Filip Granek – Management Board President
- Jacek Olszański – Management Board Member.

As at the Report Date, the Management Board performed its duties in the same composition.

Supervisory Board

As at the Balance Sheet Date, the Supervisory Board (SB) performed its duties in the following composition:

- Wiesław Rozłucki, PhD – Chairman of the Supervisory Board, an independent Supervisory Board Member
- Bartosz Wojciechowski, PhD – SB Deputy Chairman
- Beata Turlejska – SB Member
- Piotr Lembas – an independent SB Member
- Prof. Herbert Wirth – an independent SB Member

On June 30, 2026, in connection with the Annual General Meeting of the Company approving the financial statements for the fiscal year 2025, the terms of office of the current Members of the Supervisory Board expired.

Accordingly, at its Annual General Meeting held on 30 June 2026, the Company adopted a resolution determining that the Supervisory Board for the new term of office would comprise five members and appointed the following persons to the Supervisory Board for the new term of office:

- Wiesław Rozłucki – Supervisory Board Chairman
- Bartosz Wojciechowski – Deputy Chairman of the Supervisory Board
- Beata Turlejska – Supervisory Board Member
- Piotr Lembas – Supervisory Board Member
- Herbert Wirth – Supervisory Board Member.

As at the Report Date, the Supervisory Board performed its duties in the same composition.

Audit Committee:

As at the Balance Sheet Date, the Audit Committee (AC) performed its duties in the following composition:

- Piotr Lembas – Chairman of the Audit Committee, an independent AC Member
- Wiesław Rozłucki – Member of the Audit Committee, an independent AC member
- Professor Herbert Wirth – Member of the Audit Committee, an independent AC Member

On June 30, 2026, the Supervisory Board of the Issuer appointed Members of the Audit Committee for a new term of office, as follows:

- Piotr Lembas – Chairman of the Audit Committee, an independent AC Member
- Wiesław Rozłucki – Member of the Audit Committee, an independent AC member
- Professor Herbert Wirth – Member of the Audit Committee, an independent AC Member

As at the Report Date, the Audit Committee performed its duties in the same composition.

Management and supervisory bodies of the Group

Members of the Management Board of the subsidiary XTPL Inc.

The Management Board was appointed on November 24, 2023.

The term of office of the Management Board is joint and the term of office is indefinite

In the period from January 1, 2026 to June 30, 2026, the Management Board was composed of:

- Filip Granek – President and CEO, Treasurer
- Urs Berger – Secretary
- Stan Lewandowski – Assistant Secretary

The composition of the Management Board remained unchanged until the date of preparation of this Report.

Management Board members of the subsidiary TPL Sp. z o.o.

The Management Board was appointed on May 10, 2024.

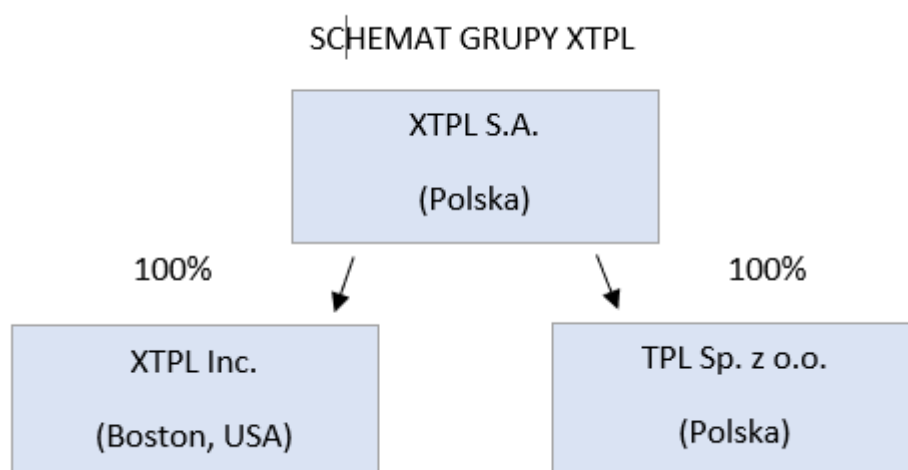
In the period from January 1, 2026 to June 30, 2026, the Management Board was composed of:

- Jacek Olszański – Management Board President, CEO

The composition of the Management Board remained unchanged until the date of preparation of this Report.

5.5 Key information about the Group

Structure of XTPL Group as at the Report Date:



Details of the subsidiary XTPL Inc.

Business name:	XTPL Inc.
Country:	United States
Registered Office:	Boston
Address:	Greentown Labs 444 Somerville Ave Somerville, MA 02143 USA
NIP:	001726856

Details of the subsidiary TPL Sp. z o.o.

Business name:	TPL Sp. z o.o.
Country:	Poland
Registered Office:	Wrocław
Address:	The Company's registered office address is ul. Legnicka 48E, 54-202 Wrocław, Poland
KRS number:	0000553991
Court designation:	District Court for Wrocław Fabryczna in Wrocław, 6th Commercial Division of the National Court Register
REGON:	361312719
NIP:	8943061516

5.6 Changes in the Group organization

Not applicable. In the Reporting Period, no changes were made in the organization of the Group.

5.7 Branches

Not applicable. Neither the Parent Company nor its Subsidiary have any branches.

5.8 Products, business model, strategy and development outlook

The Company generates revenue from the sale of proprietary products:

- Ultra-Precise Dispensing System (UPD System)

Developed by the Issuer, the UPD System product line is a modular UPD dispensing device for integration with industrial systems. In this way, industrial integrators and end customers can print functional structures with high resolution and packing density. These innovative printing modules with compatible nanoinks enable the ultra-precise creation of conductive lines on the customer's selected technological substrate in low and high-volume applications. The UPD System integrates all the functions required by the XTPL® UPD technology along with electronic control and the proprietary XTPL® UPD Process Control Software package. In addition to the strong market interest in the evaluation of UPD System, XTPL is conducting advanced talks on the commercialization of UPD System solutions with three global producers of consumer electronics (in Europe, South Korea and the USA) and five industrial integrators and producers of industrial machines (in Taiwan, South Korea, China and the USA).

As of the Report Date, the Company has sold and delivered 13 UPD product line units.

- Delta Printing System (DPS)

The Delta Printing System is an independent research and development and prototype system designed to test the capabilities of XTPL's UPD technology on various substrates and with the use of the Issuer's nanoinks. The role of the device is also to promote the Issuer's technology among global opinion leaders from the deep-tech industry – including the best academic and scientific centers as well as R&D institutes of electronics manufacturers. The Issuer began the commercialization of this business line late in 2020/ early in 2021.

As of the Report Date, the Company has sold and delivered 46 DPS product line units.

- High-Performance Materials (HPM)

Since the start of the commercialization of nanoinks developed by the Company's internal R&D department, the XTPL materials line has been developed as a complementary and at the same time independent business line. During this time, the Company has reported a significant increase in activity in terms of the nanoinks on offer alongside expansion of the customer base and improving sales performance. The offer of this business includes both conductive nanopastes with a unique formula enabling the full use of the potential of the UPD method, as well as a line of inks and pastes based on silver nanoparticles intended for use in other printing technologies, such as inkjet printing, LIFT (Laser Induced Forward Transfer), aerosol printing (with pneumatic systems) and micro-dispensing.

As at the Report Date, the Company sold HPM line products in over 123 transactions (375 since the beginning of commercialization of nanoinks – HPM from the EMEA, USA and Asia regions) to customers in 23 countries, gaining the trust of 81 returning customers.

In 2025, as part of its product portfolio, the Issuer offered within the HPM line a new innovative product: conductive paste based on gold nanoparticles. In this way, the XTPL offer currently includes inks and pastes based on two different types of metallic nanoparticles: silver and gold.

- ODRA

The ODRA device (previously referred to under the working name DPS+) constitutes XTPL's fourth business line, filling the gap between the DPS (Delta Printing System) laboratory devices and industrial UPD modules. The standalone system is designed for High-Mix, Low-Volume (HMLV) industrial manufacturing, i.e., diversified production in small batches.

Key features of ODRA:

1. Potential for repeat orders: professional users typically require more than one ODRA system, which differentiates this product line from DPS (typically one device per client).
2. User profile: industrial clients, including defense sector contractors – in contrast to DPS, which is primarily used by laboratories, research institutes, and R&D centers.

BUSINESS MODEL:

- **LICENSING:** The Company develops a technological solution dedicated to a particular application field, which is licensed to a partner who on its basis builds devices that allow the technology to be used in industry. In this case, the Company generates revenue from license fees related to the sale of devices equipped with the developed technology.

- **STRATEGIC PARTNERSHIP AND DISTRIBUTION AGREEMENTS:** The Company develops a technological solution dedicated to a particular application field; the solution is then commercialized in cooperation with a strategic partner under a joint venture agreement.

- **SALE OF PRODUCTS** The Company conducts product sales through its in-house sales team, which maintains direct contact with a range of customers interested in the Company's products and solutions across its business lines: DPS devices, UPD modules, ODRA systems, and HPM (nanoinks).

The Company also operates its own Demo Center in Boston and a Demo Center in Taiwan operated jointly with Manz Asia.

- **INTERNATIONAL DISTRIBUTOR NETWORK** Starting from 2021, the Company began building a distribution network that will facilitate the promotion of XTPL technologies and products on the Issuer's most important markets.

The choice of the optimal business model depends on the specific customer in the particular application field. Current talks take into account all of the above-mentioned business models, and the appropriate model is selected during the relationship-building process.

5.9 A concise description of the Issuer's significant achievements or failures during the period covered by the Report, together with a list of the most important events concerning the Issuer

5.9.1 Issuer's progress and achievements in the commercialization of technologies and products

In the first half of 2026, the Company focused on strengthening its position as a provider of precision additive technology in the display, semiconductor, printed circuit board, and flexible electronics industries. As a result of these activities, it achieved significant progress in the commercialization of its technology and products.

Strategic partnership with Manz Asia

In February 2026, the Company entered into a strategic partnership agreement with Manz Asia. Manz Asia is a leading manufacturer of advanced semiconductor equipment, employing approximately 380 engineers and specialists, with more than 40 years of experience in automating manufacturing processes for the semiconductor and display sectors. The company specializes in panel-level packaging, including Fan-Out Panel-Level Packaging (the "FOPLP"), Through Glass Via (the "TGV"), and IC substrates technologies. It maintains operational structures in Taiwan (Taoyuan), China (Suzhou), and India (New Delhi), as well as a dedicated Semiconductor Innovation R&D Center in Taoyuan.

Under the agreement, Manz Asia purchased a Delta Printing System from XTPL, which was installed at Manz's Semiconductor Innovation R&D Center in Taoyuan, Taiwan. At this center, XTPL and Manz Asia have the opportunity to jointly conduct technology demonstrations and evaluations of ultra-precise dispensing for industrial clients in the advanced semiconductor packaging sector. Both partners contribute their respective customer bases interested in precision printing technology to the collaboration.

In the long term, the partnership encompasses the potential integration of UPD technology with Manz Asia machinery as part of dedicated implementation projects at customer facilities. At the same time, Manz Asia assumed the role of distributor for XTPL's products and services in Taiwan and India, where it has operated for nearly 20 years with a specialized sales and technical support team.

Taiwan is one of the key global semiconductor technology markets and one of XTPL's strategic markets. The Company is currently conducting an advanced evaluation project in collaboration with a leading Taiwanese semiconductor manufacturer. The partnership with Manz Asia significantly reduces the distance to decision-makers and innovators in the local industrial ecosystem. The joint Demo Center in Taoyuan enables the evaluation of XTPL technology in close proximity to potential clients, which serves as a key factor in the procurement processes of major industrial players in the region. For XTPL, the partnership with an established local entity represents an optimal market entry model for Asian markets, which complements the wholly owned subsidiary model successfully deployed in the United States (XTPL Inc., Boston) and enables faster market penetration at significantly lower capital expenditures.

The first sale of the ODRA system

In March 2026, the Company received its first order for the ODRA system. The ODRA device (previously known under the working title DPS+) represents XTPL's fourth business line, bridging the gap between DPS laboratory devices and industrial UPD modules. This standalone system is designed for High-Mix, Low-Volume (HMLV) industrial production – that is, customized production in small batches. Key features of ODRA include: potential for repeat orders, industrial customers, defense sector counterparties, and a unit price of USD 400,000–USD 500,000.

The first buyer of the ODRA system is an industrial client based in Silicon Valley (California, USA), specializing in advanced semiconductor packaging and providing prototyping and HMLV manufacturing services for demanding clients in the technology and defense sectors. The client holds ITAR (International Traffic in Arms Regulations) certification, enabling collaboration with defense sector contractors. It is also a member of a prestigious international R&D consortium focused on advanced semiconductor packaging in Silicon Valley. This client previously purchased a Delta Printing System and has been using it for over a year to perform an initial evaluation of XTPL technology. The purchase of the ODRA system represents an important validation of this technology's effectiveness. The client transitioned from a prototyping device to a more advanced, production-oriented tool to expand its own service offering. There is potential that following the successful installation and validation of the first system, the client will purchase additional ODRA units.

The profile of ODRA's first future user, its client portfolio, and its ITAR certification create significant potential for XTPL technology in projects executed for the defense sector. The Company previously signaled interest from defense sector entities in UPD technology, which resulted in the sale of a DPS system to a US industrial client in the defense sector. An additional DPS system unit was sold to the University of Massachusetts Lowell, which operates the Raytheon-UMass Lowell Research Institute (RURI). Potential applications include electromagnetic shielding for drones, high-frequency communications for radar systems, and repair of advanced microelectronic components in near-field battlefield environments.

First sale of a UPD module to an industrial client in Japan

In June, the Company confirmed an order for a UPD module from a publicly listed Japanese entity with nearly forty years of experience in designing and delivering advanced, automated industrial equipment for the global electronics and semiconductor sectors. The UPD module will be integrated into a prototype industrial machine built by the Client and used in yield management processes (improving production yields) for advanced HDI/UHDI printed circuit boards (PCBs) and semiconductor substrates related to the advanced packaging area. This represented XTPL's first sale of equipment to Japan. The order was the result of a completed technology

evaluation and approximately one year of developing relations between the parties. The project entered the most advanced phase of the implementation process—the fourth stage, i.e., the construction of a prototype industrial machine integrated with the UPD module, preceding the decision on industrial implementation (stage five). Consequently, the order expanded the most advanced portion of XTPL's industrial pipeline and broadened it into a new geography. A key factor in the Client's decision is XTPL's unique capability for ultra-precise dispensing of copper traces – a material significantly more challenging to dispense precisely than the silver dominant in modern flat panel display (FPD) applications. The ordered module features a more advanced specification and design than the modules used in FPD applications, translating into approximately twice the unit sales value. The sale is supported by XTPL's local distributor in Japan, Printed Electronics Corporation (PEC).

Sale of Delta Printing system with a dedicated laser system to a new industrial partner in Japan

Subsequent to the balance sheet date, another order from the Japanese market was confirmed. The order is for a DPS system equipped with a dedicated laser system enabling the laser sintering of printed copper traces. The client is a Japanese manufacturer of advanced automated industrial equipment for the global electronics and semiconductor industries, with several decades of experience in designing and supplying such solutions to customers worldwide.

The DPS device serves as a laboratory demonstrator of Ultra-Precise Dispensing technology and as a tool for its independent validation by the Client. Together with the dedicated laser system, it will be utilized in yield management processes (improving production yields) for advanced structures used in the field of advanced packaging, including advanced HDI/UHDI PCBs and semiconductor substrates, using copper as the conductive material. The order is a result of successful technology validation conducted jointly by the Client and XTPL at the Company's laboratory in Wrocław and marks the project's progression to the third of five stages in XTPL's industrial implementation process, under which the Client initiates independent validation of the Company's technology in its own R&D laboratory. Subject to positive results, the subsequent stage involves ordering a UPD module and integrating it into the Client's prototype industrial machine (stage four), preceding the decision on full industrial implementation of XTPL technology (stage five).

The sale is supported by XTPL's local distributor in Japan, Printed Electronics Corporation (PEC).

Framework order for 10 UPD modules for advanced display (FPD) technology, as part of the continuation of the first industrial deployment of XTPL's technology in China

Also subsequent to the balance sheet date, the Company received a frame agreement order for 10 UPD modules in the area of flat panel display (FPD) technology, which will be used to build additional industrial machines operating on the production line of the end client – one of the largest FPD manufacturers in China. The UPD modules will be utilized in yield management processes (improving production yields) in ultra-high-resolution modern FPDs.

The order represents the next stage of the Issuer's first-ever industrial implementation of UPD technology, initiated in January 2025, under which the Company fulfilled an order for an initial batch of 6 UPD modules, delivered to the End Client and successfully integrated with industrial equipment for yield management processes. The current order confirms the continuation of this cooperation within a multi-year implementation project.

Key achievements and progress in research & development

The key achievements and progress in research & development in the reporting period included:

1. Development of high-concentration nanoparticle copper-based inks (pastes) dedicated to defect repair in advanced PCBs: HDI (High Density Interconnect) and Ultra HDI (UHDI).
2. Development of high-concentration nanoparticle gold-based inks (pastes) for applications in the MedTech (medical technology) and Biotech (biotechnology) sectors.
3. Development of Ultra-Precise Dispensing (UPD) technology for TSV filling using XTPL-developed silver pastes to achieve ultra-high aspect ratios of up to 14:1
4. Development of technology to extend the operational lifetime of nozzles with an orifice diameter of 1.5 μm to at least 5 days of industrial operation.
5. Development of a microelectrode printing technique for the electrical characterization of 2D materials.
6. Design, construction, and delivery to the client of a UPD printing module in the PRO version.
7. Work on the implementation of projects within the NPD (New Product Development) process corresponding to the development roadmap of DPS devices, UPD modules, and HPM materials.

During the reporting period, the R&D Team worked on developing a copper nanoparticle-based paste with a high solid content, compatible with UPD technology. The developed paste is dedicated to defect repair in advanced PCBs: HDI (High Density Interconnect) and Ultra HDI (UHDI). The Cu nanoparticle-based paste enables:

- repair of open defect lines in conductive traces;
- precise reconstruction of the repair profile in accordance with the dimensions of the original trace;
- printing of very narrow structures with a width of 3–25 μm while maintaining a high aspect ratio;
- operation on various substrate types, such as glass, silicon, organic substrates, including ABF, and display components;
- material deposition using the Ultra-Precise Dispensing method.

Work on improving the Cu nanoparticle-based paste will also continue in the next reporting period.

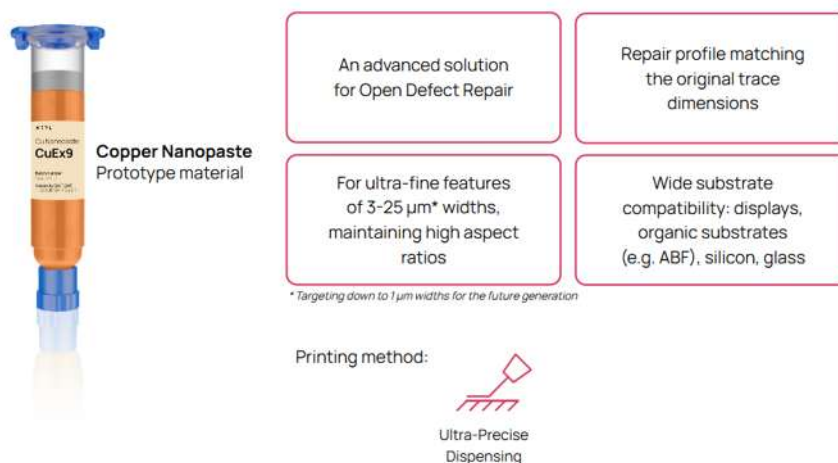


Fig. Summary of the Au90 product intended for printing in UPD technology and commercially available dispensers.

During the reporting period, the R&D Team also worked on improving a formulation based on gold nanoparticles with a metal content above 90%. It is designed for use in precision printed electronics, particularly in the high-precision printing and deposition of electrodes in sensors for applications in the MedTech (medical technology) and Biotech (biotechnology) sectors. The Au 90 paste enables precise printing of microstructures with complex geometry based on a DPS printer, and thanks to its high gold content, it

enables efficient deposition of a large amount of conductive material in one iteration. Thanks to its unique properties that prevent micro-nozzle clogging, it is an ideal product for depositing fine details on various substrates, such as glass, PCBs and foils (e.g. PET, Kapton). During the reporting period, a technique was developed for printing conductive paths with a width of 1.5–3 µm and spacing between paths down to 0.6 µm, which is currently unattainable using any other printing technology.

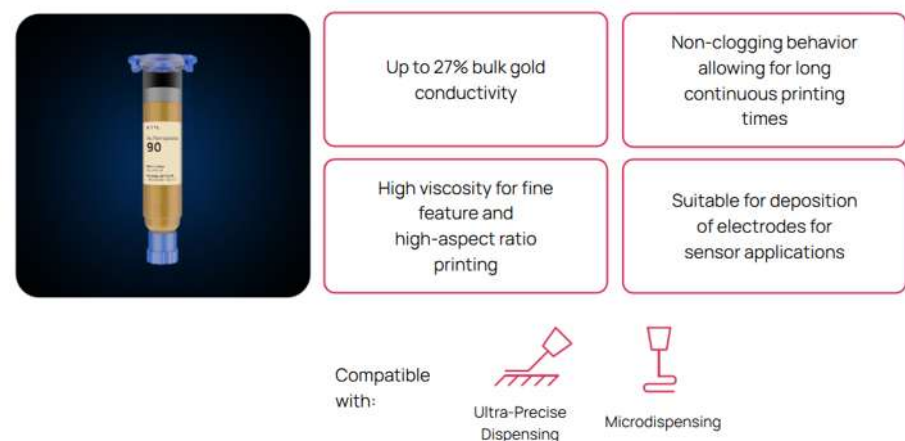


Fig. Summary of the Au90 product intended for printing in UPD technology and commercially available dispensers.

During the reporting period, research and development activities were carried out to demonstrate the feasibility of applying Ultra-Precise Dispensing (UPD) technology for filling Through-Silicon Via (TSV) structures using silver pastes developed at XTPL, achieving structures with an exceptionally high aspect ratios of up to 14:1. A uniform via filling was achieved, resulting in conductive electrical connections with a resistance in the range of 2.94–5.53 Ω TSV⁻¹ for vias fabricated in a 280 µm-thick silicon substrate. The studies also included preparation for subsequent stages of technology validation, which are critical for advanced microelectronics applications. In parallel, efforts were undertaken to enhance process scalability and production throughput. Overall, the work confirmed the potential of Ultra-Precise Dispensing (UPD) technology as a next-generation approach to TSV fabrication, offering a simplified process flow and a reduced number of post-processing steps.

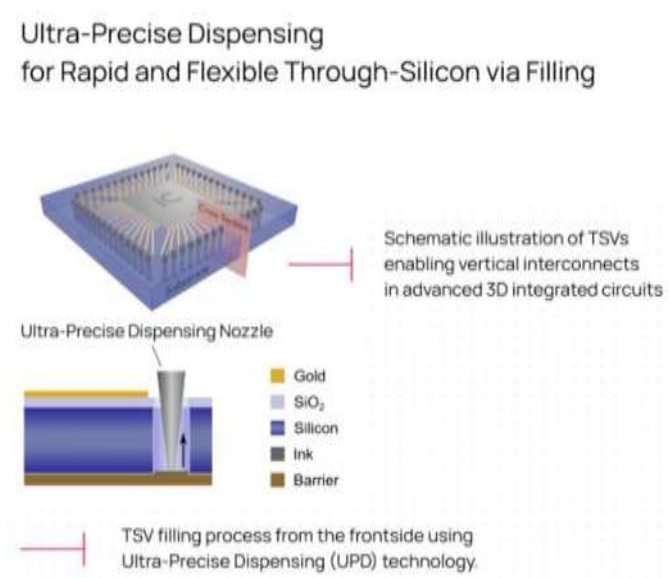
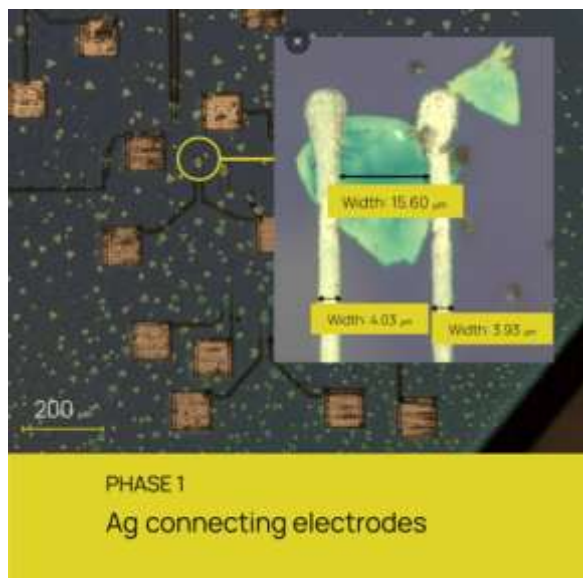


Fig. Diagram of the Through-Silicon Via (TSV) filling process using Ultra-Precise Dispensing (UPD) technology, together with an example application of TSVs in advanced 3D integrated circuits.

Development work was also conducted in the area of direct microelectrode printing for the electrical characterization of 2D materials, such as graphene, MoS₂, and NbS₂. As part of the project, XTPL's Ultra-Precise Dispensing technology was used to deposit conductive electrodes directly onto NbS₂ flakes deposited on a SiO₂/Si substrate. Structures with widths down to 1 µm were achieved, confirming the capability for fast, flexible, and maskless fabrication of electrical contacts without the need for complex lithographic processes.

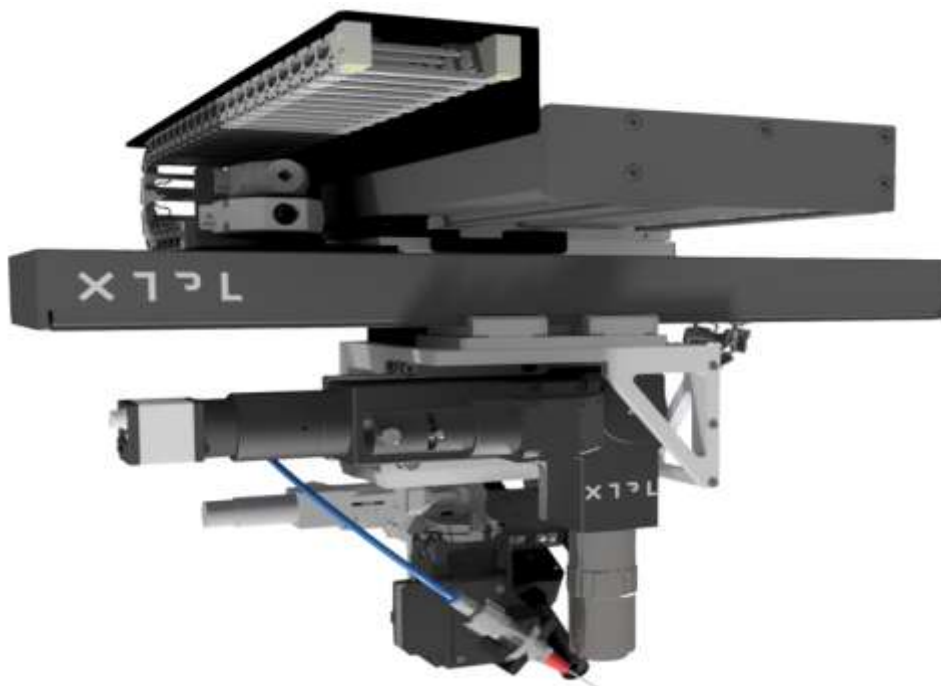


During the reporting period, work was carried out to develop a technology for extending the operational lifetime of nozzles with an orifice diameter of 1.5 µm to at least 5 days of industrial operation. The developed prototype solution is currently being tested at an industrial customer site in a microOLED display defect repair application.

During the reporting period, research and development activities were completed, along with the construction of the first UPD printing module in the PRO version for industrial integration, as part of an ongoing technology evaluation with a customer from the United States (one of the world's four largest manufacturers of large industrial machines for next-generation electronics producers, included in the NASDAQ 100 index, supplying

its solutions globally to leading semiconductor and FPD manufacturers). The UPD PRO module features an enhanced configuration and has been engineered for specialized applications identified by the U.S. client through its market research. The UPD PRO module is characterised by the following features:

- a fully integrated system equipped with a printhead and control subsystems, designed for integration into industrial machinery;
- a main working area of 300 × 300 mm with high nozzle positioning accuracy, extended with additional calibration motors;
- advanced optical systems for imaging the printing process;
- an integrated microscope with adjustable properties tailored to specific applications;
- industrial interfaces and communication protocols with dedicated software.



During the reporting period, work was initiated on the development and construction of additional UPD PRO modules, which will form part of the ODRA system being built for an industrial customer headquartered in Silicon Valley, USA. The customer specializes in advanced semiconductor packaging, providing services to clients from the technology and defense sectors, including leading companies listed in the S&P 500 and Nasdaq-100 indices, as well as global defense groups.

In the first half of 2026, three scientific papers utilizing XTPL Ultra-Precise Dispensing technology were published or accepted for publication:

1. *Bio-integrated μ Bots with overtone ultrawideband magnetoelectric antennas for wireless telemetry* – in a paper published in Science Advances, XTPL CL85 silver paste was used to form direct interconnects between antennas and a ceramic PCB, as an alternative to conventional wire bonding in implantable telemetry devices.
2. *Periodically Loaded Coplanar Waveguide-based Filters Fabricated via Ultra-Precise Deposition for Neurological Interfaces* – UPD technology was used to print silver RF filters and an encapsulation layer on a rigid-flex PCB designed for implantable neurological interfaces. Lines with a width of approximately 70 μm were achieved, along with durability exceeding 500 bending cycles.
3. *Metal-Insulator-Metal Ag/SnO₂/Al₂O₃/Ag Diodes Fabricated by Ultraprecise Dispensing and Atomic Layer Deposition* – MIM tunnel diodes fabricated using printed silver electrodes and ALD-deposited insulating layers were presented. The structures demonstrated low zero-bias resistance and high responsivity, which are significant for applications in rectenna systems. The structures demonstrated low zero-bias resistance and high responsivity, key for applications in rectenna systems.

Milestones achieved by the Issuer in H1 2026

1. Achieving printed gold conductive paths with widths of 1.5–3 μm and spacing between paths down to 0.6 μm , which remains unattainable using other conventional printing technologies.

Fabrication of technology demonstrators confirming the feasibility of applying Ultra-Precise Dispensing (UPD) technology for TSV filling using XTPL-developed silver pastes to achieve ultra-high aspect ratios of up to 14:1

3. Construction and delivery to the customer of the first UPD printing module in the PRO version, intended for advanced microelectronic applications requiring ultra-precise dispensing of functional materials.
4. Securing a recommendation for funding under the FENG.05.01-IP.01-004/25 call, Track B: Digital Technologies and Innovations within Deep Tech, organised by the National Centre for Research and Development ("NCBR"), for a project developed by the Issuer entitled "Development of Additive Technology for the Integration of Photonic Integrated Circuits for Artificial Intelligence Applications".
5. Fabrication of technology demonstrators confirming the feasibility of applying UPD technology to repair defects in advanced HDI/UHDI PCBs.

5.9.2 Issue of securities

In the first half of 2026, the Company decided to initiate actions aimed at securing funding for the Company based on raising funds through the issuance of new shares (ESPI Current Report No. 3/2026 of February 9, 2026).

The Company issued 300,000 series Y shares with a nominal value of PLN 0.10 (ten groszy) and a total nominal value of PLN 30,000.00 (thirty thousand zloty) ("Series Y Shares"). The Series Y Shares were issued pursuant to resolution No. 03/03/2026 of the Extraordinary General Meeting of the Company of March 9, 2026 on increasing the Company's share capital by issuing series Y ordinary bearer shares (fully disapplying shareholders' preemption rights), amending the Company's Articles of Association and applying for the admission and introduction of those shares to trading on the regulated market (ESPI Current Report No. 20/2026 of April 10, 2026). The subscription for Series Y Shares was completed on March 24, 2026, whereby 300,000 Series Y Shares were subscribed for, and the Company's Management Board made a declaration on determining the share capital in the Company's Articles of Association, in such a way that the Company's share capital amounts to PLN 294,987.70 and is divided into 2,949,877 ordinary bearer shares with a nominal value of PLN 0.10. Amendments to the Company's Articles of Association in this respect were registered in the National Court Register on March 30, 2026 (ESPI Current Report No. 18/2026 of March 30, 2026).

The Series Y Shares were registered with KDPW S.A. and admitted to trading on the regulated market operated by the Warsaw Stock Exchange (GPW S.A.) and introduced to trading on the regulated market on April 13, 2026 (ESPI Current Report No. 21/2026 of April 13, 2026).

During the Reporting Period, the Company did not issue any bonds.

In the second half of the year, the Company issued a current report regarding its intention to raise financing through the issuance of Series Z shares and the establishment of authorized capital (ESPI Current Report No. 34/2026 dated September 1, 2026, and No. 36/2026 dated September 18, 2026).

The Management Board proposes to increase the Company's share capital through the issuance of no less than 198,462 and no more than 400,000 Series Z Shares, with a nominal value of PLN 0.10 each, at an issue price of PLN 65.00 per Series Z Share. The issuance of Series Z Shares is to be conducted via private subscription, as referred to in Article 431 § 2 item 1 of the Commercial Companies Code, carried out by way of a public offering benefiting from exemptions from the requirement to prepare, approve, and publish a prospectus provided for in Regulation (EU) 2017/1129 of the European Parliament and of the Council.

The Management Board intends for the issue of the Series Z Shares to be conducted in a manner allowing the Company's shareholders holding at least 0.5% of the total number of the Company's shares (each individually) as of the end of the record date for participation in the New EGM (the "Eligible Investors") to exercise priority in subscribing for the Series Z Shares in a number sufficient to enable each Eligible Investor to maintain a percentage interest in the total number of votes at the General Meeting of the Company that is not lower than

the percentage interest held by such Eligible Investor as of the end of the record date for participation in the New EGM. The foregoing will apply provided that the Eligible Investors submit declarations of interest in subscribing for the Series Z Shares and subsequently accept the offers to subscribe for the Series Z Shares addressed to them. The submission of an offer to subscribe for the Series Z Shares shall be at the sole discretion of the Company's Management Board, provided that the Management Board shall use due care to offer the Series Z Shares to those Eligible Investors who meet the conditions set out above, if the settlement of the subscription for the Series Z Shares by a given Eligible Investor can be technically completed within the timeframe specified by the Company's Management Board (the "Priority Mechanism").

5.9.3 Funding

In April 2026, the Company signed a grant agreement with the National Centre for Research and Development ("NCBR") under the call FENG.05.01-IP.01-004/25, Track B: Digital technologies and innovations within deep technologies, organized by the National Centre for Research and Development (ESPI Current Report No. 22/2026 dated April 17, 2026). The co-financing relates to the project developed by the Company entitled "Development of Additive Technology for Photonic Integrated Circuit Integration for Artificial Intelligence Applications". The main objective of the Project is the development, construction, and validation of a prototype next-generation printing system designed for heterogeneous integration of photonic and electronic integrated circuits (PIC + EIC) within advanced packaging processes. The developed technology will form part of the European value chain in the field of advanced semiconductors.

The total value of the project amounts to PLN 18,286,399.84, including a recommended co-financing amount of PLN 10,091,591.16. Project implementation period: May 1, 2026 – December 31, 2029.

5.9.4 Issuer's activities designed to protect its intellectual and industrial property

In the process of commercialization of technologies developed by the Company, an important role is played by intellectual property (IP), which constitutes XTPL's competitive advantage. The development of an IP portfolio and its appropriate protection are crucial to the company's market position and significantly affect its value. XTPL technological solutions are protected from the moment of patent filing.

The Company distinguishes five patent groups for its technology and products based on that technology:

1. UPD process – patents describing the ultra-precise deposition process or devices used for this process
2. Nanoinks – patents protecting various nanoink formulations
3. Software – patents protecting the solutions implemented in the software that controls the printing devices
4. Application fields – patents describing solutions to specific technological problems using the UPD method
5. Characterization and quality control – patents related to the characterization and quality control of selected components of the printing devices

In H1 2026, the Company continued activities aimed at development of its patent cloud, specifically:

1. On February 4, 2026, the Company received notification that the United States Patent and Trademark Office (USPTO) had granted approval of the patent claims for the invention entitled "Metallic nanoparticle composition and method of dispensing metallic nanoparticle composition".
2. On February 12, 2026, the Company received notification that the China National Intellectual Property Administration (CNIPA) had granted approval of the patent claims for the invention entitled "Methods for forming features by dispensing metal nanoparticle compositions from inkjet printheads and metal nanoparticle compositions for inkjet printing".

In addition, after the Reporting Period, the Company obtained the following industrial and intellectual property protection:

1. On July 7, 2026, the Company received notification regarding the approval by the United States Patent and Trademark Office (USPTO) of patent claims for the invention entitled "A method for additive manufacturing and an additive manufacturing apparatus."

The Company has adapted its process of filing patent application to the recommendations of the patent law firms cooperating with it. The recommendations help create patent applications of the highest quality and, as a result, strengthen the level of protection of the Company's intellectual property.

As at the Report Date, the Company has 48 patents approved, covering e.g. Japan, China, South Korea, Malaysia, Germany and the USA. As at the Report Date, the Company had trademarks registered with the Patent Office of the Republic of Poland and the European Union Intellectual Property Office, as well as in China, the United States and the UK.

The building of a patent cloud for the proprietary technology and products is an essential part of the Company's strategy, which raises the Issuer's credibility among potential industrial clients. The patent protection obtained as a result of the filings will increase the value of the potential commercialization of the Company's technology with respect to industrial implementations. The Company plans to file more patent applications for inventions to be developed in the course of current and future research and development.

5.9.5 Issuer's participation in events dedicated to capital market investors

In order to implement the corporate governance and communication standards and to ensure constant and equal access to information about the Company for all stakeholders, and to meet their needs, the Issuer undertakes numerous activities in the area of investor relations.

The Company focuses on regular communication with the capital market, including through a constantly updated website with a separate investor relations section where information materials are posted (including press releases and presentations) and through the publication of selected video materials on YouTube. Furthermore, the Company tries to provide fast and reliable answers to the questions received from individual investors. In order to facilitate contact with the Company, the "Contact" tab on the investor relations site contains contact details for institutional investors, analysts and journalists. The Company publishes earnings calls in Polish and English on its corporate channel on YouTube: <https://www.youtube.com/@xtplsas/videos..>

In the first half of 2026, the Company held a number of meetings with investors in connection with the accelerated book-building process conducted between March 10 and 12, 2026. An offer to subscribe for a total of 300,000 Series Y ordinary bearer shares was directed to selected qualified investors or to fewer than 150 natural or legal persons other than qualified investors. The accelerated bookbuilding process was completed on March 12, and as a result the issue price of one Series Y share was set at PLN 65.00. Strong interest from both existing and new investors resulted in a low single-digit discount of approximately 2% to the volume-weighted average share price over the 30-day period preceding the General Meeting that approved the share issue.

On April 30, 2026, the Company organized two earnings calls for investors and all capital market stakeholders, during which the Company's Management Board discussed the Issuer's financial results for the fourth quarter of 2025 and the entire year 2025. The first meeting was held in Polish and the other in English. During both video conferences, the Management Board of XTPL S.A. presented the financial and operational results of the

Company, summarized the most important events and achievements of this period and answered investors' questions in the Q&A section.

Link to the conference (PL): <https://www.youtube.com/watch?v=i-4lqx3Vybc>

Link to the conference (ENG): <https://www.youtube.com/watch?v=sUDWI5hDoro>

The Issuer is monitoring upcoming investor events in which to participate to be able to showcase its achievements with respect to technology and its commercialization, financial performance and development prospects.

Investor events occurring after the Balance Sheet Date

On July 2, 2026, the Company organized an educational webinar for investors and all capital market stakeholders dedicated to Ultra-Precise Dispensing (UPD) technology developed at XTPL. The meeting was attended by Filip Granek, CEO of XTPL S.A., and Piotr Kowalczewski, Intellectual Property Director at XTPL S.A., and was moderated by Michał Masłowski, Vice President of the Association of Individual Investors (SII). The webinar was hosted on the SII channel.

During the webinar, investors learned, among other topics, about the megatrends driving the development of advanced electronics, how Ultra-Precise Dispensing (UPD) technology works, how UPD differs from other material deposition methods, the key performance metrics that set XTPL technology apart, and example applications of UPD in semiconductors, displays, advanced packaging, defect repair, optics, and electromagnetic shielding.

Link to the webinar (PL): <https://www.sii.org.pl/19156/aktualnosci/czat-inwestorski/webinar-edukacyjny-xtpl-technologie-ultra-precise-dispensing-upd-i-jej-zastosowania.html>

The Issuer is monitoring upcoming investor events in which to participate to be able to showcase its achievements with respect to technology and its commercialization, financial performance and development prospects.

5.9.6 Issuer's participation in industry events

38th NEPCON Japan (Tokyo, Japan, January 2026) XTPL participated in NEPCON Japan together with its local distributor, presenting Ultra-Precise Dispensing technology and conducting activities aimed at strengthening business relationships in the Asian market.

Lodz University of Technology, Department of Semiconductor and Optoelectronic Devices (Łódź, Poland, January 2026) Representatives of XTPL visited the Department of Semiconductor and Optoelectronic Devices at the Lodz University of Technology, an entity conducting research in the field of microelectronics and optoelectronics.

ICONN 2026 (Sydney, Australia, February, 2026) XTPL participated in the ICONN 2026 conference through its distributor, promoting XTPL's solutions for advanced microelectronics and deep-tech applications.

ECS Brokerage Event (Brussels, Belgium, February 2026) An XTPL representative participated in the ECS Brokerage Event, a gathering of the European Electronic Components and Systems community aimed at consortium building ahead of Chips JU calls for proposals. The Company delivered a presentation and held discussions regarding cooperation on European research and development projects.

innoLAE 2026 (Cambridge, United Kingdom, February 2026) XTPL participated in innoLAE 2026 together with its distribution partner. During the conference, XTPL's Business Development Manager delivered a presentation entitled: "Ultra-Precise Dispensing: A Direct-Write Solution for Advanced Semiconductor Interconnects", focused on the application of XTPL's technology in the area of advanced semiconductor interconnects.

LOPEC 2026 (Munich, Germany, February 2026) XTPL participated in LOPEC 2026, presenting ultra-precise printing solutions for the printed, additive, and flexible electronics markets.

iMAPS Device Packaging (Phoenix, AZ, USA, March 2026) An XTPL representative participated in the 22nd iMAPS Device Packaging Conference, dedicated to advanced semiconductor packaging as well as assembly and interconnect technologies.

EPIC Technology Meeting on Photonics for Defense: Securing the Future at Exosens (Brive, France, March 2026) An XTPL representative participated in a closed EPIC (European Photonics Industry Consortium) technology meeting dedicated to photonics for the defense sector, hosted at the headquarters of Exosens. The Company engaged in discussions with photonics technology suppliers and integrators regarding the applications of XTPL technology in defense electronics.

APEX 2026 (Anaheim, USA, March 2026) The Company participated in IPC APEX EXPO 2026 together with its distribution partner. XTPL was represented on site by the Managing Director for the North American region, conducting business development activities and presenting the Company's technology.

SEMICON China 2026 (Shanghai, China, March 2026) XTPL participated in SEMICON China 2026 together with its local distributor, presenting Ultra-Precise Dispensing technology for advanced microelectronics and semiconductor applications.

INFRACHIP Industry hands-on AFM training (Cork, Tyndall, Ireland, March–April 2026) Representatives of XTPL participated in practical training on atomic force microscopy (AFM), organized at the Tyndall National Institute as part of the European INFRACHIP project, which supports the development of competencies and infrastructure in semiconductor technologies.

ICDT (Chongqing, China, March–April 2026) An XTPL representative participated in the ICDT 2026 conference (International Conference on Display Technology), organized by SID China and covering the entire display technology supply chain. The Company delivered a presentation entitled “Ultra-Precise Dispensing for Advanced Display Manufacturing: From Pixel Repair to Wrap-Edge Interconnects”.

Rapid + TCT (Boston, USA, April 2026) XTPL participated in the RAPID + TCT 2026 trade show, one of North America's premier events dedicated to additive manufacturing and industrial 3D printing.

Event organized by Georgia Institute of Technology (USA, May 2026)

Representatives of XTPL Inc., Urs Berger and Kyle Homan, are participating in a closed event organized by Georgia Tech, dedicated to technologies for advanced microelectronics and semiconductors.

Chemnitz Seminar "Electronic Packaging and Applications" (Chemnitz, Germany, May 2026) An XTPL representative participated in a seminar organized by Fraunhofer ENAS jointly with TU Chemnitz and Silicon Saxony, dedicated to advanced electronic packaging and heterogeneous integration.

IEEE Build-Up Substrate Symposium (BUSS) (Silicon Valley, USA, May 2026)

During IEEE BUSS 2026, Urs Berger delivered a presentation titled “Micron-Level Dispensing for the Next Generation PCB & Display Repair”, focused on the use of Ultra-Precise Dispensing technology for the repair of ultra-thin conductive structures in advanced displays and UHD PCBs.

IMAPS IBERIA 2026 (Barcelona, Spain, June 2026)

XTPL participated in IMAPS IBERIA 2026, presenting the Company's solutions for the advanced microelectronics and semiconductor technology markets.

NextFlex Innovation Day 2026 (Mountain View, USA, June 2026)

XTPL participated in NextFlex Innovation Day 2026 with its own booth. The Company was represented by Urs Berger, presenting XTPL's solutions for the advanced electronics and microelectronics markets.

TechBlick USA 2026 (Mountain View, USA, June 2026)

XTPL Inc. participated in TechBlick USA 2026 with its own booth. The Company was represented by Urs Berger and Kyle Homan, conducting activities related to the presentation of XTPL's technology and the development of business relationships in the North American market.

JPCA Show 2026 (Tokyo, Japan, June 2026)

XTPL was represented at JPCA Show 2026 by its partners Alpha and PEC, presenting the Company's solutions for advanced PCB and microelectronics applications.

MINaPAD Forum 2026 (Grenoble, France, June 2026)

XTPL will participate in the MINaPAD 2026 conference dedicated to advanced microelectronics and packaging technologies. During the event, Filip Granek will deliver a presentation entitled:

“Ultra-Precise Dispensing for Advanced Microelectronics Packaging: Materials Versatility and Long-Term Process Stability”.

The presentation will focus on Ultra-Precise Dispensing technology in the context of advanced microelectronics packaging, with particular emphasis on material compatibility and long-term process stability.

OE-A Meeting North America (Mountain View, CA, USA, June 2026) An XTPL representative participated in a meeting of the OE-A (Organic and Printed Electronics Association), which brings together companies and research institutes from the printed, organic, and flexible electronics industry.

EPoSS Annual Forum 2026 (Braga, Portugal, June 2026) XTPL participated in the EPoSS Annual Forum 2026, the annual meeting of the European technology platform dedicated to smart systems integration. During the event, Filip Granek delivered a presentation entitled: “Ultra-Precise Dispensing as a Circuit Editing Tool in Advanced Semiconductor Packaging,” concerning the application of XTPL technology for circuit repair in advanced semiconductor packaging.

Laser Sintering Workshop Hamamatsu / Fraunhofer ENAS (Chemnitz, Germany, June 2026) An XTPL representative participated in a workshop on digital electronics printing and laser sintering of functional inks, organized by Fraunhofer ENAS jointly with Hamamatsu Photonics.

Military University of Technology (WAT) (Warsaw, Poland, June 2026) Representatives of XTPL visited the Military University of Technology, which conducts research in areas including optoelectronics, laser technology, and defense sector technologies, to discuss opportunities for research collaboration.

Industry events occurring after the Balance Sheet Date

UK Semiconductors 2026 (Sheffield, UK, July 2026) XTPL participated in the UK Semiconductors 2026 conference, the UK's annual meeting dedicated to semiconductor research, ranging from materials and devices to commercial applications. The Company was present as a sponsoring partner alongside its UK distributor, Semitronics.

SEMICON Taiwan 2026 (Taipei, Taiwan, September 2026)

The Company plans to participate in SEMICON Taiwan 2026 together with its partner Sigma and with the support of PAIH. XTPL will present solutions for the advanced microelectronics and semiconductor markets.

IMAPS 2026 (Bukowina Tatrzańska, Poland, September 2026)

XTPL is participating in the IMAPS 2026 conference with its own booth, presenting the Company's solutions for the advanced microelectronics and hybrid electronics markets.

IMAPS Symposium 2026 (Boston, USA, September/October 2026)

XTPL is participating in the IMAPS Symposium 2026 conference with its own booth. The Company is represented by Urs Berger, conducting activities related to the presentation of XTPL's technology and the development of business relationships in the North American market.

TechBlick Europe 2026 (Berlin, Germany, October 2026)

XTPL is participating in TechBlick Europe 2026 with a presentation and exhibition booth, showcasing Ultra-Precise Dispensing technology for additive electronics and advanced microelectronics applications.

Australian National Fabrication Facility Annual Forum 2026 (Australia, October 2026)

XTPL plans to participate in the ANFF Annual Forum 2026 together with its distribution partner. The Company's presence will include an exhibition booth and a planned presentation on XTPL's technology and its applications in advanced microelectronics.

SEMICON Europa 2026 (Munich, Germany, November 2026)

The Company is participating in SEMICON Europa 2026 with its own booth, conducting activities related to the presentation of XTPL's technology and the development of business relationships within the European semiconductor and advanced packaging sectors.

MRS Fall Meeting 2026 (Boston, USA, November/December 2026)

XTPL is participating in the MRS Fall Meeting 2026 conference. During the event, Urs Berger will present XTPL's solutions and technologies for advanced microelectronics and material applications.

SEMICON Japan 2026 (Tokyo, Japan, December 2026)

XTPL is participating in SEMICON Japan 2026 with its own booth, also as part of the EU Business Hub initiative, presenting the Company's solutions for the advanced microelectronics and semiconductor markets.

OE-A Delegation to India (New Delhi, Pune, Bengaluru, India, September 2026) XTPL will participate in a trade mission organized by the OE-A association to India. As part of the event, an XTPL representative will deliver a presentation during the "OE-A Symposium on Flexible and Printed Electronics: From Technology to Smart Applications" at the electronica/productronica India trade fair in Bengaluru. The purpose of the mission is to establish relationships with the Indian electronics market.

MNE Micro+Nano Engineering Conference (Interlaken, Switzerland, September 2026) XTPL will participate in the 52nd Micro and Nano Engineering Conference, a European meeting dedicated to micro- and nanofabrication and its applications in electronics and photonics. The conference program includes a poster co-authored by the XTPL team entitled "Additive Manufacturing of MicroLED Color Conversion Modules via Ultra-Precise Dispensing."

Binghamton University Electronics Packaging Symposium (Binghamton, NY, USA, September 2026) An XTPL representative is participating in the 37th symposium dedicated to electronics packaging at Binghamton University, organized in cooperation with the IEEE Electronics Packaging Society. This year's edition focuses on packaging for artificial intelligence applications.

MSPO (International Defence Industry Exhibition) (Kielce, Poland, September 2026) XTPL is participating in the 34th International Defence Industry Exhibition in Kielce, the largest defence industry trade fair in Central and Eastern Europe. During the event, an XTPL representative will deliver a presentation entitled "Transparent EMI Shielding Printed on Curved Optics for Defense Applications" as part of the Photonics4Defense session.

Dual-Use Sector Mission to Norway: Oslo and Kongsberg (Oslo, Norway, September 2026) An XTPL representative will participate in a dual-use technology sector trade mission organized by PAIH in cooperation with the Polish Embassy in Oslo. The mission will include meetings with the Norwegian defense and technology industries, including at the industrial hub in Kongsberg.

Taitronics 2026 – National Stand (Taipei, Taiwan, October 2026) XTPL will participate in the TAITRONICS (Taipei International Electronics Show) trade fair at the national stand organized by PARP, presenting the Company's solutions for the professional electronics and microelectronics markets.

Industrial Print Integration Conference (Neuss, Germany, November 2026) An XTPL representative will participate in the IPI conference, organized by the ESMA association, dedicated to the implementation of industrial and functional printing in areas including electronics, automotive, and biomedical applications.

IMAPS UK (The RF, Microwave and Photonics Packaging) (Newport, UK, November 2026) XTPL will participate in the IMAPS UK RaMPoP (RF, Microwave and Photonics Packaging) conference, dedicated to the packaging and assembly of RF, microwave, and photonic devices.

IMAPS Italy Workshop – High Reliability Packaging for Avionics, Aerospace & Defense (Milan, Italy, November 2026) XTPL will participate in the IMAPS Italy workshop at Politecnico di Milano, dedicated to high-reliability packaging for avionics, aerospace, and defense. An XTPL representative will deliver a presentation entitled “Additive Manufacturing of 1–10 µm Metal Structures for RF and Microwave Interconnects and EMI Shielding”.

5.9.7 Other

During the reporting period, Ms. Agata Gładysz-Stańczyk submitted her resignation from the position of Member of the Supervisory Board of the Company with immediate effect, citing new professional responsibilities as the reason (ESPI Current Report No. 23/2026 of April 22, 2026).

On June 30, 2026, the Annual General Meeting of the Company appointed the Management Board, the Supervisory Board, and Members of the Audit Committee for a new term of office, with the following composition:

Management Board

1. Filip Granek – Management Board President
2. Jacek Olszański – Management Board Member

Supervisory Board:

1. Wiesław Rożłucki – Supervisory Board Chairman
2. Bartosz Wojciechowski – Deputy Chairman of the Supervisory Board
3. Beata Turlejska – Supervisory Board Member
4. Piotr Lembas – Supervisory Board Member
5. Herbert Wirth – Supervisory Board Member.

Audit Committee:

1. Piotr Lembas – Chairman of the Audit Committee, an independent AC Member
2. Wiesław Rożłucki – Member of the Audit Committee, an independent AC member
3. Professor Herbert Wirth – Member of the Audit Committee, an independent AC Member

This was communicated by the Company in ESPI Current Report No. 25/2026 of June 30, 2026.

The composition of the Management Board, Supervisory Board and Audit Committee remained unchanged until the date of preparation of this Report.

5.9.8 Events occurring after the Balance Sheet Date

The Management Board of XTPL S.A. announced that on July 3, 2026, the Company confirmed the acceptance of an order for a Delta Printing System alongside a dedicated laser system enabling laser sintering of printed copper conductive traces, placed by a new industrial partner from Japan, which is equivalent to concluding a sales agreement (ESPI Current Report No. 30/2026 of July 3, 2026).

The client is a Japanese manufacturer of advanced automated industrial equipment for the global electronics and semiconductor industries, with several decades of experience in designing and supplying such solutions to customers worldwide.

The DPS device serves as a laboratory demonstrator of Ultra-Precise Dispensing technology and as a tool for its independent validation by the Client. Together with the dedicated laser system, it will be utilized in yield management processes (improving production yields) for advanced structures used in the field of advanced packaging, including advanced HDI/UHDI PCBs and semiconductor substrates, using copper as the conductive material.

The order is a result of successful technology validation conducted jointly by the Client and XTPL at the Company's laboratory in Wrocław and marks the project's progression to the third of five stages in XTPL's industrial implementation process, under which the Client initiates independent validation of the Company's technology in its own R&D laboratory. Subject to positive results, the subsequent stage involves ordering a UPD module and integrating it into the Client's prototype industrial machine (stage four), preceding the decision on full industrial implementation of XTPL technology (stage five).

This marks another sale of an XTPL product to Japan and the second – alongside the project reported in June 2026 – independent industrial project for the Company in this market. The Issuer reported the first sale of a UPD module to Japan, covering a project at the fourth stage of the industrial implementation process, in which the UPD module is integrated into the customer's prototype industrial machine (Current Report No. 26/2026 of June 11, 2026). The current order concerns another customer and is at an earlier, third stage of this process, but in a similar, strategic application area. The parallel development of two independent industrial projects in the Japanese market confirms the repeatability of XTPL's commercial model and the growing interest in the Company's technology within the semiconductor and advanced packaging sectors.

The sale is supported by XTPL's local distributor in Japan, Printed Electronics Corporation (PEC). Delivery of the DPS device along with the laser system is scheduled for the second half of 2026, and the Company expects to recognize revenue from its sale during this period. Revenue generated from the fulfillment of the order will have a positive impact on XTPL S.A.'s financial results for 2026, while the potential for further cooperation may serve as a significant premise for continued sales growth in future periods.

As part of the development and commercialization of UPD modules, the Company confirmed the acceptance of an order for 10 UPD modules in the field of advanced display technology (FPD) as a continuation of the first industrial implementation of XTPL technology in China (ESPI Current Report No. 32/2026 of July 23, 2026). The devices will be used to build additional industrial machines operating on the production line of the end customer – one of the largest FPD manufacturers in China. The UPD modules will be utilized in yield management processes (improving production yields) in ultra-high-resolution modern FPDs. The order represents the next stage of the Issuer's first-ever industrial implementation of UPD technology, initiated in January 2025, under which the Company fulfilled an order for an initial batch of 6 UPD modules, delivered to the End Client and successfully integrated with industrial equipment for yield management processes (ESPI Current Report No. 1/2025 of January 3, 2025). The current order confirms the continuation of this cooperation within a multi-year implementation project.

On August 17, 2026, the District Court for Wrocław-Fabryczna in Wrocław, 6th Commercial Division of the National Court Register, registered amendments to the Company's Articles of Association resulting from Resolution No. 16/06/2026 of the Annual General Meeting of the Company held on June 30, 2026 on amending the Articles of Association of XTPL S.A. ("Issue Resolution").

Under the Issue Resolution, amendments were made to § 4, § 8, § 14, § 15, § 19, § 20 and § 21 of the Company's Articles of Association.

In connection with ESPI Current Report No. 27/2025 of September 25, 2025, regarding the update of the Company's Strategy, and ESPI Current Report No. 3/2026 of February 9, 2026, regarding the intention to obtain financing and initiate the share issuance process, the Management Board of XTPL S.A. informs that on

September 1, 2026, it took a decision to commence activities aimed at: (i) obtaining further financing for the Company by conducting an issuance of new shares, and (ii) providing the Company with the possibility of flexible future capital raising through the establishment of authorized capital (ESPI Current Report No. 34/2026 of September 1, 2026, and ESPI Current Report with subsequent amendment of assumptions No. 36/2026 of September 18, 2026).

The Management Board's intention is to convene an Extraordinary General Meeting of the Company on October 19, 2026 (ESPI Current Report No. 38/2026 of September 18, 2026), which would decide, in particular, on: (i) increasing the Company's share capital through the issuance of Series Z ordinary bearer shares by way of a private subscription conducted via a public offering, with the complete exclusion of pre-emptive rights for existing shareholders, amending the Company's Articles of Association, and seeking the admission and introduction of Series Z shares to trading on the regulated market operated by the Warsaw Stock Exchange S.A., the dematerialization of Series Z shares, and the authorization to enter into an agreement for the registration of Series Z shares with the securities depository; (ii) presenting the opinion of the Management Board of XTPL S.A. regarding the draft resolution amending the Company's Articles of Association to provide authorization for the Management Board to increase the share capital within the limits of authorized capital, including the option for the Management Board to exclude shareholders' pre-emptive rights to shares and subscription warrants for every share capital increase within the limits of authorized capital, subject to the prior consent of the Supervisory Board, setting forth the justification for excluding pre-emptive rights with respect to shares and subscription warrants issued within the authorized capital and the method for determining their issue price; and (iii) adopting a resolution to amend the Company's Articles of Association by authorizing the Management Board to increase the share capital within the limits of authorized capital, including the option for the Management Board to exclude shareholders' pre-emptive rights to shares and subscription warrants for every share capital increase within the limits of authorized capital, subject to the prior consent of the Supervisory Board.

5.10 Factors and events, including extraordinary ones, having a significant impact on the standalone and consolidated financial statements

During the Reporting Period, there were no factors or events, including extraordinary ones, that would have a significant impact on the standalone and consolidated financial statements.

5.11 Management Board's position on the implementation of financial forecasts

The Management Board's position regarding the possibility of achieving the previously published performance forecasts for a given year, in the light of the results presented in the Report in relation to the forecast results, i.e. preliminary estimates of consolidated revenues from the sale of products and services achieved by the Company in Q2 2026 and H1 2026, published in ESPI Current Report 31/2026 of July 22, 2026, is as follows: The preliminary data disclosed to the public were substantially in line with the actual data.

5.12 Significant court and administrative proceedings

During the reporting period, there were no significant proceedings pending before any court or other public authority.

5.13 Non-arms length transactions with related entities

Not applicable. As part of the group, no transaction was made with any related party on non-commercial terms.

5.14 Guarantees given

Not applicable. Neither the Issuer nor its Subsidiary provided any loan guarantees in the Reporting Period.

5.15 Employment and information about the Issuer's employee team

As at the Balance Sheet Date, the Company employed 49 people.

As at the Balance Sheet Date, the Group employed 51 people.

Our Team:

The development of XTPL ultra-precise printing technology is a success of the Company's entire team, which, using its interdisciplinary knowledge and experience, keeps achieving further technological and business goals. Technological progress is the result of intensive cooperation of engineers and specialists who pool competences of many areas of technology, business and operations.

What distinguishes the XTPL technology team is its interdisciplinary knowledge in fields such as physics, optics, chemistry, mechanics, electronics and programming. The technology team represents 36.73% of all employees and carries out work in individual laboratories: Application, Nanoinks and Nanomaterials, Hardware and Software. The Production and Customer Care department plays an important role in the solution implementation process, being responsible for the production of devices, the assembly and testing of devices, and ensuring their highest quality.

The technology team is backed up by an operations team, which provides support in the areas of finance, law, HR, procurement, IT and project management. At the same time, the Marketing Department is responsible for marketing and PR/IR activities. The sales team is responsible for gaining new markets and maintaining customer relationships, while the Implementations and Customer Care team provides comprehensive user support and partnerships in the post-sales phase.

Women accounted for 38.78% of the whole XTPL team. At the same time, in the technology team, women represented 27.78% of the staff.

Team training and development:

Upskilling training courses are implemented in consultation with the team leaders and the Company's management board. Most training courses are organized on the employees' initiative. The development of the XTPL team is promoted by regular participation in domestic and foreign conferences, as well as in on-site and online industry events.

Benefits:

XTPL offers its employees a benefits package in the form of a non-wage benefits program. XTPL offers: private medical care, health & life insurance, program of awards for patent applications, employee referral program, remote working options (depending on the nature of the job), and access to the XTPL corporate library.

5.16 Other information which, in the Issuer's opinion, is important for the assessment of its personnel, asset and financial position, financial performance and their changes, as well as information which is important for the assessment of the Issuer's and the Group's ability to fulfill its obligations

The Company is making steady progress on its most advanced industrial projects and has a growing pipeline of early-stage industrial projects across key industries (semiconductors, advanced displays, PCBs) and key geographic markets (Asia, North America, Europe). Currently, there are more than 45 DPS devices and 15 industrial modules in the market. In addition, the Company is in an advanced stage of work related to the delivery of the ODRA system intended for production in the HMLV (High-Mix Low-Volume) model. In the first half of 2026, the Company expanded its portfolio of industrial projects by selling a DPS device and a UPD module to two customers in the Japanese market operating in the area of yield management for advanced printed circuit boards (HDI/UHDI PCBs) and semiconductor substrates in advanced packaging. The parallel development of two independent industrial projects in the Japanese market confirms the repeatability of

XTPL's commercial model and the growing interest in the Company's technology within the semiconductor and advanced packaging sectors. In addition, in July 2026 (ESPI Current Report No. 32/2026 of July 23, 2026), the Company confirmed the acceptance of a framework order covering 10 UPD modules, which will be used to build additional industrial machines operating on the production line of the end customer – one of the largest FPD display manufacturers in China. The order represents the next stage of the Company's first-ever industrial implementation of UPD technology, initiated in January 2025, under which the Company fulfilled an order for an initial batch of 6 UPD modules, delivered to the end client and successfully integrated with industrial equipment for yield management processes (ESPI Current Report No. 1/2025 of January 3, 2025). The current order confirms the continuation of this cooperation within a multi-year implementation project.

At the same time, the pace of the first industrial implementation has been slower than originally anticipated, and the Company's customers have indicated a timing shift relative to the assumptions initially communicated to the Company regarding the expected timeframe of market demand for subsequent technology nodes requiring high-resolution printing. As a result, the conversion of the remaining active industrial projects into sales may take longer than expected.

Due to longer-than-expected commercialisation processes, the Management Board of the Company has identified a funding gap in 2026. To secure financing for 2026, the Management Board indicated in Current Report 27/2025 of September 25, 2025, that it is conducting four parallel processes in the following areas:

- debt financing;
- co-financing R&D projects through grant funding;
- acquiring a strategic investor who would take a minority stake in the Company;
- a capital increase and a share issue directed to the market.

The Management Board considers the most likely path to finance the Company's growth to be a combination of all of the above-mentioned instruments, which vary in size and timing of deployment. Between March 10 and 12, 2026 the Company conducted a private placement of 300,000 ordinary bearer shares. In the book-building process, the issue price was set at PLN 65 per share. As a result, the Company raised PLN 19.5 million in gross proceeds from the share issue. The purpose of the share issue was to finance the Company's growth by continuing the implementation of industrial projects and the related further R&D activities, developing new products – including ODRA, next generations of printing modules and printing inks – expanding sales structures, intensifying marketing activities, and maintaining a safe level of inventory. In the Management Board's view, these actions should result in achieving PLN 100 million in sales and reaching sustainable profitability for the Company by 2028. In addition, on March 11, 2026, the Issuer received information on the recommendation for funding under call FENG.05.01-IP.01-004/25, Path B: Digital Technologies and Innovations within Deep Tech, organised by the National Centre for Research and Development ("NCBR"), for a project developed by the Issuer entitled "Development of Additive Technology for Photonic Integrated Circuit Integration for Artificial Intelligence Applications". The main objective of the Project is the development, construction, and validation of a prototype next-generation printing system designed for heterogeneous integration of photonic and electronic integrated circuits (PIC + EIC) within advanced packaging processes. The developed technology will form part of the European value chain in the field of advanced semiconductors. The recommended funding amount of approximately PLN 10 million will significantly support R&D activities related to new products through the end of 2029.

On September 1, the Company announced the signing of a letter of intent with a potential Taiwanese strategic investor with experience in semiconductor investments (ESPI Current Report No. 34/2026 of September 1, 2026). Under the letter of intent, the strategic investor expressed interest in an equity investment in the Company consisting of the subscription for new shares, i.e.: 198,462 ordinary bearer series Z shares at an issue price of PLN 65.00 per share, for an aggregate issue price of PLN 12.9 million. A potential investment by the industry investor would positively impact the Company's cash position and strengthen its business relationships in the Asian market. On September 18, the Company published a report (ESPI Current Report

No. 36/2026) regarding a change in the offering assumptions, modifying certain terms, i.e., the number of offered shares to a range of not less than 198,462 and not more than 400,000 shares, and expanding the subscription offer to include existing shareholders of the Company holding at least 0.5% of the total number of the Company's shares as at the record date for participation in the Extraordinary General Meeting of the Company, convened for October 19, 2026. The Management Board intends for the issue of the series Z shares to be conducted in a manner allowing the Company's shareholders holding at least 0.5% of the total number of the Company's shares (each individually) as of the end of the record date for participation in the New EGM to exercise priority in subscribing for the Series Z Shares in a number sufficient to enable each eligible investor to maintain a percentage interest in the total number of votes at the General Meeting of the Company that is not lower than the percentage interest held by such eligible investor as of the end of the record date for participation in the New EGM. For the Company, this potentially implies higher proceeds from the planned share issuance than originally anticipated.

Funds raised from the share issue and grant financing stabilise the Issuer's financial position for at least the next 12 months; however, the Company remains actively engaged in securing additional forms of financing. Negotiations with institutions providing debt financing are ongoing, at various stages of advancement. Taking the above into account, as of the date of approval of these financial statements, the Management Board does not identify any circumstances indicating a threat to the Company's ability to continue as a going concern.

5.17 Factors that, in the Issuer's assessment, will affect the results achieved by the Issuer and the Group over the perspective of at least the next quarter

Factors which may affect the Company's and the Group's operations and results in the following quarters:

- Signing commercial contracts, and progress of work on paid evaluation initiatives, licensing or joint-development agreements in relation to the Issuer's technology;
- Ability to protect and safeguard intellectual and industrial property, including the number and scope of submitted patent applications;
- Favourable trends in the electronics industry;
- Acquiring additional financing in the form of grants and subsidies supporting the Issuer's research and development activities;
- Economic consequences of the war in Ukraine;
- Economic effects associated with the political and economic situation in the Middle East region;
- Situation in financial markets.

5.18 Description of the main threats and risks related to the remaining months of the financial year

5.18.1 Risk factors and threats related to the Company's and the Group's business environment

5.18.1.1 Macroeconomic risk

The Company's and the Group's activity depends on the macroeconomic situation in the markets in which the Company plans to start the sale of its products and services, primarily in the United States, Asia and Western Europe. Profitability of the Company's operations will depend, inter alia, on the economic growth, consumption and investment level (particularly in the electronics sector), fiscal and monetary policy, inflation, and especially the level of expenditures on consumer electronics in those countries. All these factors may have an impact on the Company's and the Group's financial results, and thus may also affect implementation of the Company's development strategy.

The Issuer's level of exposure to risk: low

5.18.1.2 Currency risk

Due to the fact that the Company's and the Group's clients are international entities, most of the Company's revenues related to the commercialization of technology are settled in foreign currencies (mainly the euro and the US dollar). At the same time, as the Company is based in Poland, most of its ongoing expenses will be settled in the Polish zloty. As a result, the Company may be exposed to a significant FX risk. Volatility of exchange rates may primarily cause changes in the value of the Company's revenues and receivables after their conversion into PLN.

Despite the significant weakening of the Polish currency related to the outbreak of the war in Ukraine, the Company and the Group do not see currency risk as a significant threat to the expected level of their operating profitability. The weakening of the Polish zloty strengthens the cash position of the Company as an exporter. A significant portion of purchases of materials and components for the production of printers is settled in euro. As a result, revenues from foreign currency sales constitute a natural hedge against exchange rate movements. As and when required, the Company and the Group will resort to FX risk management instruments available in the banking market.

The Issuer's level of exposure to risk: low

5.18.1.3 New technology risk

The market in which the Company and the Group operate is characterized by rapid development of technologies. For this reason, the development of the Company's and the Group's operations entails constant tracking and analysis of new market trends and identification of emerging potential competitors and technological solutions they implement. There is a risk that if the current market trends change, the Company and the Group will be forced to look for new applications for its technology outside of what it previously saw at its core business or to incur expenditures to make its existing solutions more competitive. Likewise, the Company and the Group can not rule out that in the future a new technology will be developed which will make the solutions offered by the Company and the Group unattractive for potential clients. Materialization of this risk will mean additional costs, which will adversely affect profitability of the Company's and the Group's operations. In addition, the need to perform additional work may delay the moment of commercialization of the Company's and the Group's products.

The Issuer's level of exposure to risk: medium

5.18.1.4 Competitive risk

The Company and the Group operate in a very attractive market of modern technologies characterized by a steadily growing demand. In this market, there is a number of players whose experience and capital resources are higher than those of the Company. As the market is changing fast, there is a risk of a new entity emerging whose offer will be more innovative than the Company's and the Group's offer. A competitive edge may be obtained by implementing innovative, unique solutions that are attractive for prospective clients in utility and economic terms.

At present, the Company is not aware of any solutions that would technically offer better parameters for the ultra-precise printing of nanomaterials. However, it cannot be ruled out that a new entity or a solution will emerge that will surpass the Company's technology in some or all key parameters. There is also a risk that the Company and the Group will not be able to respond quickly or effectively enough to the changing market environment, and as a consequence the solutions offered by the Company and the Group will be considered less competitive. Materialization of this risk may have a negative impact on the sale of the Company's and the Group's products and services and, in consequence, on its trading performance.

The Issuer's level of exposure to risk: medium

5.18.1.5 Risk related to the development of the SARS-CoV-2 pandemic

Due to the market in which the Company operates, the situation related to the coronavirus threat fundamentally does not affect the Issuer's operational activity. The Company has developed a number of procedures depending on the level of risk and applies them as appropriate depending on the situation. Office workers may perform their duties remotely (they are provided with a company phone with Internet access and a laptop). Technology staff work in compliance with all the standards announced by state authorities. Some technology staff are involved in the development of new grant applications, and therefore may also partly work from home. As a rule, all meetings take place using video- or teleconferencing. The planned operations related to the shipment of products take place in conformity with the requirements in force in the country of destination.

The Issuer's level of exposure to risk: low

5.18.1.6 Sources of supply

The Company commercializes and develops its proprietary nanoprinting technology. Due to the advancement of the technology, the Company makes use of a wide range of products and services available in the market, the key ones being measurement, research, conductive nanoinks formulation development and patent protection services as well as services related to rental of specialist equipment and laboratories. The great diversity and variability of the Company's R&D work is reflected in the number of sources of supply it uses. As a result, in 2022, the Company reached a 56% threshold of purchases from one supplier – provider of research services and lessor of laboratories and office space (100%). At the same time, the Company steadily increases its laboratory equipment and limits the use of outsourced measurement and research services.

In the manufacturing process, the Company sources materials and chemical reagents, which are the key inputs for the production of highly conductive inks offered by XTPL S.A. and uses suppliers of components and materials in the process of making the Delta Printing System devices.

The chemicals suppliers base is highly fragmented. No supplier exceeds 20% of total purchases in this category. In addition, there are many high-quality materials available in the market and there is no risk of dependence on any single source of supply. Importantly, the vast majority of chemicals are purchased in the domestic market, so potential problems with global supply chains have only limited impact on the Company.

In terms of materials and components for the production of printers, one supplier reached 32% of the total value of purchases in this category. The other suppliers do not exceed 15% of the total turnover. The Company constantly forges relationships with new entities and builds a base of alternative suppliers.

The Issuer's level of exposure to risk: medium

5.18.2 Risk factors related to the Company's and the Group's operations

5.18.2.1 Risk related to the technology commercialization process

The Company's and the Group's business model provides for a gradual commercialization of the technology of printing ultra-thin conductive lines for various applications in printed electronics. At present, the commercialization process already covers printing devices and nanoinks. In terms of industrial implementations on clients' production lines, the target business model is that the Company and the Group will commercialize their technological solutions through licensing or will manage the whole value chain, i.e. manufacture, product marketing, distribution and provision of specialized services tailored to the client's needs. The choice of the commercialization model will depend on the results of negotiations with the partner, specific nature of the particular application field and the Issuer's assessment regarding effectiveness of each of the possible commercialization methods in that field.

Currently, the Company is involved in nine industrial implementation projects, which confirms the market need for solutions offered by the XTPL technology. In addition, the Company signed and carries out an agreement

with Nano Dimension Ltd. to develop a next generation conductive nanoink for industrial applications in the firm's products designed for the production of PCBs. This agreement is the first agreement signed with an industrial partner and is a milestone in the Company's development.

However, there is a risk that introduction of devices into individual markets will not be in line with the current expectations due to, for example, a lack of or insufficient demand in target countries, misidentification of potential clients' needs, misidentification of legal conditions, incomplete adaptation of the Company's products to the requirements of foreign markets, an ineffective promotional campaign or an unexpected emergence of a competitor. Occurrence of the above events may stifle the Company's and the Group's growth dynamics, adversely impacting their operations and financial position.

The Issuer's level of exposure to risk: high

5.18.2.2 Risk of failure to achieve revenues

At the present stage of the Company's development, this risk should be considered negligible. In the financial year, the Company significantly increased its sales revenues compared to the previous year. The main stream of those revenues was the sale of printing devices. The Company intends to develop this product group rapidly, also by building its distribution network (external distributors) all over the world. At the same time, the Company steadily increases its revenues from the sale of inks and other consumables for printers. Furthermore, the Company has an agreement with an industrial entity to develop a next generation conductive nanoink. The first revenues in this respect were recognized in 2022.

The Issuer's level of exposure to risk: medium

5.18.2.3 Risk of low product quality

The Company's and the Group's business model providing for a gradual introduction of the technology of printing ultra-thin conductive lines for various applications in printed electronics gives rise to a risk of defects, insufficient product quality or unsatisfactory performance of the technology at the initial phase of its commercialization. However, the emergence of unforeseen defects and problems should be taken into account. Such situations may result in a negative first reception of the Company's and the Group's products and, consequently might dampen interest in and demand for the product. As a result, the Company and the Group might not receive revenues in the expected amount.

The Issuer's level of exposure to risk: high

5.18.2.4 Risk related to the business development model and the failure deliver the Company's and the Group's strategy

The goal of the business model is commercialization of the Company's ultra-precise technology of printing a wide range of nanomaterials. The Company is already commercializing its first products – technology carriers. It is also carrying out nine projects focused on implementing technologies on partners' production lines. However, in this area — which offers the greatest potential — the Company has not yet established a repeatable business model. Due to the geographic and economic conditions in the market, the Company will develop its business presence mainly in the United States, Asia and Western Europe. The Company intends to build its market position through organic growth, primarily based on further development of its technology. Due to a number of factors, the Company is unable to guarantee in full that its business development model will work. The Company's future in the broadly understood printed electronics market depends on its ability to create and implement a successful long-term development strategy and to continue to develop its technology. The risk of making bad decisions resulting from improper assessment of the situation or the Company's inability to adapt to changing market conditions, incorrect strategic assumptions, including in relation to the developed technology and the adopted commercialization plan and the degree of demand from

potential clients, may mean that the business development model will not be effective and the future financial results might be lower than currently expected.

The Issuer's level of exposure to risk: high

5.18.2.5 Risk related to the difficulty with acquiring experienced and specialized employees

The high level of technological advancement of the Company's research leads to a constant increase in the requirements regarding skills and experience of employees. Next to technology, the engineering and scientific staff is the Company's most valuable asset. The pace and quality of the Company's R&D is directly related to the skills of specialists who form the R&D team. The Company employs engineers from the fields of chemistry, physics, electronics, mechanics, material engineering, programming and numerical simulations. Nearly in all these fields, the number of specialists available for hiring is not high. As regards acquisition of the best specialists, the Company competes with firms both in Poland and abroad.

As the Company expands the size of its operations, this factor may be of particular importance in the future as it might limit the development potential. Difficulties in sourcing employees may delay work or force the Company to abandon certain projects.

The Issuer's level of exposure to risk: medium

5.18.2.6 Risk of losing key team members

The Company's activity is based on a narrow team of people with relevant know-how who pool competencies in engineering and technical, financial management and strategic management of the Company. For this reason, losing key people may adversely affect the Company's further business, its financial, property and economic condition as well as its development prospects as it may impair the Company's potential to sell its products, develop its technology, win new contracts and properly manage already existing contracts.

Most of the Company's personnel are people employed in operational roles. They do tasks which require expertise, skill and education. The Company is exposed to the risk of losing some of its operational staff, which might weaken the organizational foundations of the Company's business. These situations might result in the Company's stability being undermined and force it to raise remuneration levels in order to retain employees. As a result, it may affect the Company's operating costs.

The Issuer's level of exposure to risk: medium

5.18.2.7 Risk of dependence on future counterparties

Due to the specific nature of industrial implementation projects (with high contract values), commercialization of the first projects will result in major dependence on individual clients. Hence, the Company conducts projects with many partners in various markets and application fields.

The sale of printing devices and consumables does not pose such a risk due to the one-sided nature of transactions in the case of printers and the fragmented market in the case of consumables.

Due to the fact that the Company supplies advanced technical equipment, there is a risk of dependence on suppliers of materials and components. The Company tries to diversify supply sources, forges partnerships and builds a base of alternative suppliers, but it should be kept in mind that with such technically advanced devices, the replacement of components is also subject to risk in terms of efficiency of the manufactured devices.

The Issuer's level of exposure to risk: medium

5.18.2.8 Risk of potential disclosure of confidential information on technology

Implementation of the Company's strategy depends, inter alia, on the fact that the holders of confidential information, particularly that concerning development and technological processes related to the ultra-precise printing technology. There is a risk that sensitive information will be divulged by persons connected with the

Company, which may result in the information being used by competitors, despite the intellectual property protection measures used by the Company.

The indicated risk factor may have a negative impact on the Company's business, financial position, development prospects, results and share price.

The Issuer's level of exposure to risk: low

5.18.2.9 Risk of intellectual property infringement

The Company operates in an area where regulations concerning industrial and intellectual property rights and their protection are of significant importance. At present, there are no proceedings under way regarding infringement of any industrial or intellectual property rights in which the Company would be involved. The Company intends to conduct its business in such a way as not to infringe any third party rights in this respect. However, it can not be ruled out that third parties would bring claims against the Company regarding infringement of industrial and intellectual property rights by the Company. Even if unwarranted, such claims might adversely affect the schedule of the Company's strategy implementation, and the defense against such claims may involve significant costs, which may adversely impact the Company's financial results. In addition, during work on its own patent applications, the Company carefully reviews the available literature and patents known at present. However, there is a risk of infringement of intellectual property rights related to patents that have been submitted but not published yet.

Cooperation with external partners gives rise to similar risks. Formally unauthorized entities might attempt to use the intellectual property of XTPL by either violating or attempting to circumvent the patent application. The circumstances described above may have a material adverse effect on the Company's development prospects, results and financial position.

The Issuer's level of exposure to risk: medium

5.18.2.10 Risk of technology scaling

Due to the fact that the technology underlying the printing process developed by XTPL is based on highly innovative solutions, there is a risk that an increase in its use from laboratory to industrial scale might end up unsuccessfully.

This risk may materialize due to difficulties with obtaining technology parameters in industrial production that would be equally stable as those obtained in the laboratory. In addition, there is a risk that the technology developed may not be sufficiently effective for certain production processes in industry (e.g. due to a failure to achieve satisfactory production process efficiency).

The Issuer's level of exposure to risk: high

5.18.2.11 Risk of a failure to reach the target clients and achieve sales plans

XTPL clients will include, in particular, large manufacturers of devices for the fabrication of electronics. They have long communication and decision-making channels. There is a risk that a proposition from XTPL, as a company with a short market history, will be assessed as not reliable enough. This may delay delivery of the Company's sales targets or indeed lead to a failure to acquire a targeted client. However, an increase in sales, especially the sales of printing devices, is accompanied by a steady increase in awareness of the XTPL technology, both among direct buyers, including research institutes, and indirect ones, such as industrial partners that research institutes cooperate with. In addition, the Company itself has established a number of relationships with industrial partners and is now working with them on nine projects.

The Issuer's level of exposure to risk: medium

5.18.2.12 Risk of emergence of a competitive technological solution

New technological solutions that are in competition against XTPL are constantly being developed in the global technology market. A comparison of the parameters of the currently available solutions with the parameters achieved in the XTPL technology shows, in the Company's opinion, that competitive technologies offer solutions with weaker parameters and oftentimes higher production costs compared with what is expected to be achieved by the industrial XTPL solution. The Company has undertaken measures designed to cover its technology with extensive patent protection. As at the report date, the Company's competitive risk can be described as low, as the developed solutions are less effective than those on which the Company is working at present. However, it is not possible to rule out the possibility that a more technologically advanced or more cost-effective solution might emerge in the market. There is also a risk that competitors might significantly increase their expenditures to promote available solutions. These risks may materially affect the Company's development outlook.

The Issuer's level of exposure to risk: medium

5.18.2.13 Risk of loss of financial liquidity and access to financing

As at the Report Date, the Company's revenues from the sale of products and services, supported by grant proceeds, are sufficient to secure its operating activities. However, it should be noted that except for nanoink sales, the Company has not yet achieved stable, recurring income.

There is also a risk of financing the operations when the business is taken to an industrial scale. However, the possibility of obtaining financing from several different sources should be taken into account, i.e. debt financing, grant projects and equity financing (profits and new share issues).

The Issuer's level of exposure to risk: medium

5.18.2.14 Risk of not receiving grants and subsidies

Grants and subsidies are the second source (next to share issues) of financing the Company's research and development. There is a risk of not receiving adequate grants and subsidies, which may delay research and development.

In the past, the Company entered into a grant agreement with NCBR whereby NCBR is authorized to terminate the financing in the cases enumerated in the agreement, including when (i) the Issuer refuses to undergo or hinders inspections; (ii) the Issuer has made legal and organizational changes that jeopardize the performance of the agreement or fails to inform the NCBR of its intention to make such changes; (iii) the NCBR identifies gaps in the submitted documentation on the environmental impact of the project, and such gaps are not eliminated by a stated deadline; (iv) the beneficiary fails to comply with disclosure obligations during implementation and durability period of the project; (v) irregularities, listed directly in the agreement, occur in delivery of the project. Therefore, there is a risk that NCBR might claim reimbursement of the grant provided to the Company, in whole or in part, which may affect the financial position of the Company.

The Issuer's level of exposure to risk: low

5.18.2.15 Risk of implementation of in-house technologies by the Company's potential clients

An important group of potential buyers of the technology developed by the Companies are global producers of electronic components (e.g. displays). There is a risk that these entities, which have significant technical and organizational resources, may develop their in-house nanoprinting solutions, and consequently will not be interested in the product offered by the Company.

The Issuer's level of exposure to risk: high

5.18.2.16 Risk of unforeseen events

The Company is exposed to the risk of extraordinary events, such as technical failures (e.g. of electrical networks, either internal or external), natural disasters, acts of war, etc. These events might impair the effectiveness of or disrupt the Company's operations. In such circumstances, the Company may be exposed to unforeseen costs.

The Issuer's level of exposure to risk: low

5.18.2.17 Human factor risk

In its production activity, the Company works with people employed under employment contracts and other civil law contracts. Actions performed by these persons as part of their work may lead to errors caused by improper performance of their duties. Such actions may be intentional or unintentional and may lead to disruptions and delays in the commercialization process.

The Issuer's level of exposure to risk: medium

5.18.2.18 Risk of failure of the equipment used in the Company's and the Group's operations

In its operations, the Company relies on properly working specialist equipment. There is a risk that in the event of a serious equipment failure which cannot be addressed immediately, the Company may be forced to temporarily suspend some or all of its activities until the failure is removed. Equipment failures may also lead to a loss of the data used for developing the Company's product. An interruption in business or loss of key data for a particular project may result in the Company being unable to perform its obligations under existing contracts or cause a loss of these contracts, which may adversely affect the Company's financial performance.

The Issuer's level of exposure to risk: low

5.18.2.19 Risk of insufficient insurance coverage

The Company enters into insurance contracts in the course of its activity. However, it can not be ruled out that insurance risks will materialize in the Company's activity that will go beyond the scope of insurance coverage, or unforeseen events occur that are out of scope of the existing insurance policies. Such events may have an adverse impact on the Company's trading performance.

The Issuer's level of exposure to risk: low

5.18.2.20 Risk of court and administrative proceedings

According to the available information, no court or administrative proceedings are pending against the Company that would have a significant impact on its operations. However, the Company's future sales activity will give rise to potential risks associated with possible customer claims in relation to the products sold. The Company also enters into commercial contracts with external entities whereby both parties are required to provide specified service/ consideration. This in turn gives rise to a risk of disputes and claims arising from such contracts. These disputes or claims may adversely affect the Company's reputation and, consequently, its financial results.

The Issuer's level of exposure to risk: low

5.18.2.21 Risk of related-party transactions

The Company enters into transactions with its related parties. Where competent tax authorities question the methods of how the Company has determined market conditions for related-party transactions, this may have negative tax implications for the Company, potentially causing a material adverse effect on its business, financial position and results.

The Issuer's level of exposure to risk: low

5.18.2.22 Risk of intellectual property rights and application patents

The Company's technology may be the basis for other entities to develop derivative or related technologies. There is a risk that such entities will decide to submit application patents based on the Company's technology. As a result, the Company, as the holder of the underlying patent, will have to cooperate with a third party, as the application patent holder, to ensure commercial implementation of a particular technology. In terms of intellectual property rights, the Company uses works created by persons employed under employment contracts.

The Issuer's level of exposure to risk: low

5.18.2.23 Risk related to commercialization agreements

Due to the specific nature of its operations, the Company may use various types of commercialization agreements (license agreements, JDAs, product sale agreements, joint venture agreements). However, it is not possible to rule out the market risk related to a failure to find a partner interested in purchase of the Company's products or commercialization. Market risk is also affected by changes in potential clients' strategies, changes resulting from movements in market trends and inability to reach decision makers. In addition, account should be taken of the risk of default by a contractual partner or the risk of the Issuer's failure to abide by the terms of the contract due to materialization of any of the risks described above. Should any of these circumstances occur, this may adversely affect the Issuer's operations, financial results and/or development prospects.

The Issuer's level of exposure to risk: medium

5.18.2.24 Risk of impact of the war in Ukraine on the Company's and Group's operations

The war in Ukraine did not change XTPL's operating model. The Company has not been affected by any impact of the conflict on the printed electronics market. In addition, the Company:

- is not dependent on any raw material/ component supplies from the regions of Russia, Belarus or Ukraine;
- does not conduct sales activities in the above markets. Likewise, the Company's business strategy does not envisage sales to those countries going forward;
- does not have any on-site or remote collaborators from those countries;
- is exporter of goods denominated mainly in EUR, so it is not exposed to negative effects of depreciation of the zloty;
- has not received any information from business partners from countries other than those mentioned above about their plans to introduce changes in their business activities that could adversely affect XTPL.

The Company has identified the risk that the war might impact its operations indirectly by affecting the global economy in terms of:

- reduced availability of raw materials and the related lower availability of materials and components;
- supply chain difficulties due to limitations in air transport.

The Company and its employees undertook a number of activities to help Ukrainian war refugees:

- introduced an additional day off per month for volunteering for all employees;
- published job ads on a portal dedicated to Ukrainian refugees;
- collected toys and essential items for children from an Ukrainian orphanage who came to Poland;
- offered accommodation to Ukrainian refugees;
- sewed clothes for children from Ukraine;
- helped in sorting donations at local help centers;
- donated computer equipment to the crisis management center that helps refugees;
- helped in transporting Ukrainian citizens from the railway station to their place of accommodation;

- provided material support to Ukrainian soldiers;
- paid contributions to verified fundraisers.

The Issuer's level of exposure to risk: medium

5.18.2.25 Risk of the impact of the war in the Middle East on the operations of the Company and the Group

The geopolitical situation in the Middle East has not resulted in any changes to XTPL's operating model. The Company has not been affected by any impact of the conflict on the printed electronics market. Despite having a subsidiary in the United States and business relationships with companies operating in Israel, the conflict has not affected the Company's activities in this respect.

At present, the Company does not identify any risk of the above-mentioned conflict affecting its operations.

The Issuer's level of exposure to risk: medium

5.19 BASIS OF PREPARATION OF THE INTERIM CONDENSED SEPARATE AND CONSOLIDATED FINANCIAL STATEMENTS

5.19.1 General information and basis of preparation

The half-yearly interim condensed financial statements of XTPL (standalone and consolidated) cover the period of six months ended June 30, 2026, and the comparative data for the period of six months ended June 30, 2025. They were prepared using the historical cost convention. The financial statements have been prepared on the assumption that the Company will continue in operation for at least a year from the Report Date.

At the date of approval of these financial statements, the Management Board has not identified any circumstances which would point to a risk to continuity of operations in the above period.

The financial statements have been prepared in accordance with the International Accounting Standard ("IAS") 34 Interim Financial Reporting and in accordance with the Finance Minister's Ordinance on current and financial information.

5.19.2 Currency of the financial statements

The functional currency and reporting currency of the financial statements is the Polish zloty (PLN), and the data contained in the financial statements are presented in thousands of Polish zlotys.

5.19.3 Exchange rates used in the financial statements

Exchange rates used in the financial statements	January–June 2026		January–June/ December 2025	
	EUR	USD	EUR	USD
for balance sheet items	4.2963	3.7708	4.2267	3.6016
for profit or loss and cash flow items	4.2522	3.6526	4.2208	3.8422

5.19.4 Description of significant accounting principles

The same accounting policies were applied in the preparation of these interim condensed financial statements as in the financial statements for the year 2025 published on April 29, 2026, and in the most recent quarterly financial statements prepared as of March 31, 2026 (report for Q1 2026 of May 27, 2026). There were no changes in the accounting policies or significant changes in estimates in the Reporting Period

6. SHAREHOLDING STRUCTURE

6.1 Significant shareholdings

As at the Balance Sheet Date, the shareholding structure was as follows (shareholders holding at least 5% of the total number of votes at the General Meeting):

Ref.	Shareholder	Number of shares held	% of all shares	Number of votes	% of all votes
1.	Deutsche Balaton AG	437,042	14.82%	437,042	14.82%
2.	Filip Granek, PhD	333,498	11.31%	333,498	11.31%
3	Esaliens TFI SA	303,809	10.30%	303,809	10.30%
4	ACATIS Investment	291,742	9.89%	291,742	9.89%
5	Leonarto Funds	267,564	9.07%	267,564	9.07%
6	Others	1,316,222	44.62%	1,316,222	44.62%
	TOTAL	2,949,877	100.0%	2,949,877	100.0%

** Deutsche Balaton AG and Heidelberger Beteiligungsholding AG*

As at the Report Date, the shareholding structure was as follows (shareholders holding at least 5% of the total number of votes at the General Meeting):

Ref.	Shareholder	Number of shares held	% of all shares	Number of votes	% of all votes
1.	Deutsche Balaton AG	437,042	14.82%	437,042	14.82%
2.	Filip Granek, PhD	333,498	11.31%	333,498	11.31%
3	Esaliens TFI SA	303,809	10.30%	303,809	10.30%
4	ACATIS Investment	291,742	9.89%	291,742	9.89%
5	Leonarto Funds	267,564	9.07%	267,564	9.07%
6	Others	1,316,222	44.62%	1,316,222	44.62%
	TOTAL	2,949,877	100.0%	2,949,877	100.0%

Since the date of submission of the previous periodic report by the Issuer, i.e. submission of the report for the first quarter of 2026 on May 27, 2026, there have been no changes in the ownership of significant shareholdings.

6.2 Shares held by members of management and supervisory bodies

Ref.	Name	Role	Ownership as at June 30, 2026	Shares held as at the Report Date
1.	Filip Granek, PhD	CEO	333,498	333,498
2.	Jacek Olszański	Management Board Member	9,250	9,250
3.	Wiesław Rozłucki, PhD	Chairman of the Supervisory Board	–	–
4.	Bartosz Wojciechowski, PhD	Deputy Chairman of the Supervisory Board	1,350	1,350
5.	Prof. Herbert Wirth	Supervisory Board Member	–	–
6.	Piotr Lembas	Supervisory Board Member	–	–
7.	Beata Turlejska	Supervisory Board Member	–	–

Since the date of the Issuer's previous financial report, i.e., the submission of the Q1 2026 report on May 27, 2026, there have been no changes in the ownership of the Issuer's shares by members of the Issuer's management or supervisory bodies.

7. MANAGEMENT BOARD'S STATEMENT

The Management Board of XTPL S.A. declares that, to the best of its knowledge, interim condensed standalone and interim condensed consolidated financial statements and comparable data have been prepared in accordance with applicable accounting principles and that they present a true, fair, and clear view of the assets and financial position of the Issuer and the XTPL Group, as well as their financial performance. Further, the Management Board of XTPL S.A. declares that the Management Board's half-yearly report on the activities of XTPL S.A. and the XTPL Group gives a true view of development, achievements and the situation of XTPL and the Issuer's Group (including a description of key threats and risks).

Signatures of all Management Board Members

Filip Granek
CEO

Jacek Olszański
Management Board Member

Wroclaw, September 28, 2026

8. REPORT ON THE INTERIM REVIEW OF THE CONDENSED STANDALONE AND CONSOLIDATED FINANCIAL STATEMENTS

The audit firm's report on the interim review of the interim condensed standalone and consolidated financial statements of XTPL S.A. and the XTPL Group is attached to the Report.

9. MANAGEMENT BOARD'S OPINION

Not applicable. The audit firm did not issue a qualified opinion, an adverse opinion, or a disclaimer of opinion on the standalone or consolidated financial statements of XTPL S.A. and the XTPL Group.

Signatures of all Management Board Members

Filip Granek
CEO

Jacek Olszański
Management Board Member

Wroclaw, September 28, 2026

10. STATEMENT OF THE MANAGEMENT BOARD REGARDING THE AUDIT FIRM AUTHORIZED TO AUDIT FINANCIAL STATEMENTS

The Management Board of XTPL S.A. declares that the audit firm authorized to audit financial statements, which conducted the review of the interim condensed financial statements, was appointed in accordance with applicable laws. This entity and the auditors who performed this review met the conditions for issuing an impartial and independent report on the review of the interim condensed financial statements, in accordance with applicable regulations and professional standards.

Signatures of all Management Board Members

Filip Granek
CEO

Jacek Olszański
Management Board Member

Wroclaw, September 28, 2026

11. APPROVAL FOR PUBLICATION

The report for the first half of 2026 ended June 30, 2026 was approved for publication by the Issuer's Management Board on September 28, 2026.

Signatures:

Filip Granek
CEO

Jacek Olszański
Management Board Member

Wrocław, September 28, 2026